

Scara Robot Electrical Systems

White-Paper

Updated: April 2, 2022

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Abstract

The electrical system is composed of a motherboard, a power supply and the driver control module. The driver control module receives coordinates from the motherboard and a count from the motor encoder. The motherboard is a stm32 Nucleo powered by 5V through the power supply. The power supply receives power from the wall plug and delivers power for all components including 48V to the DC brushed motor.

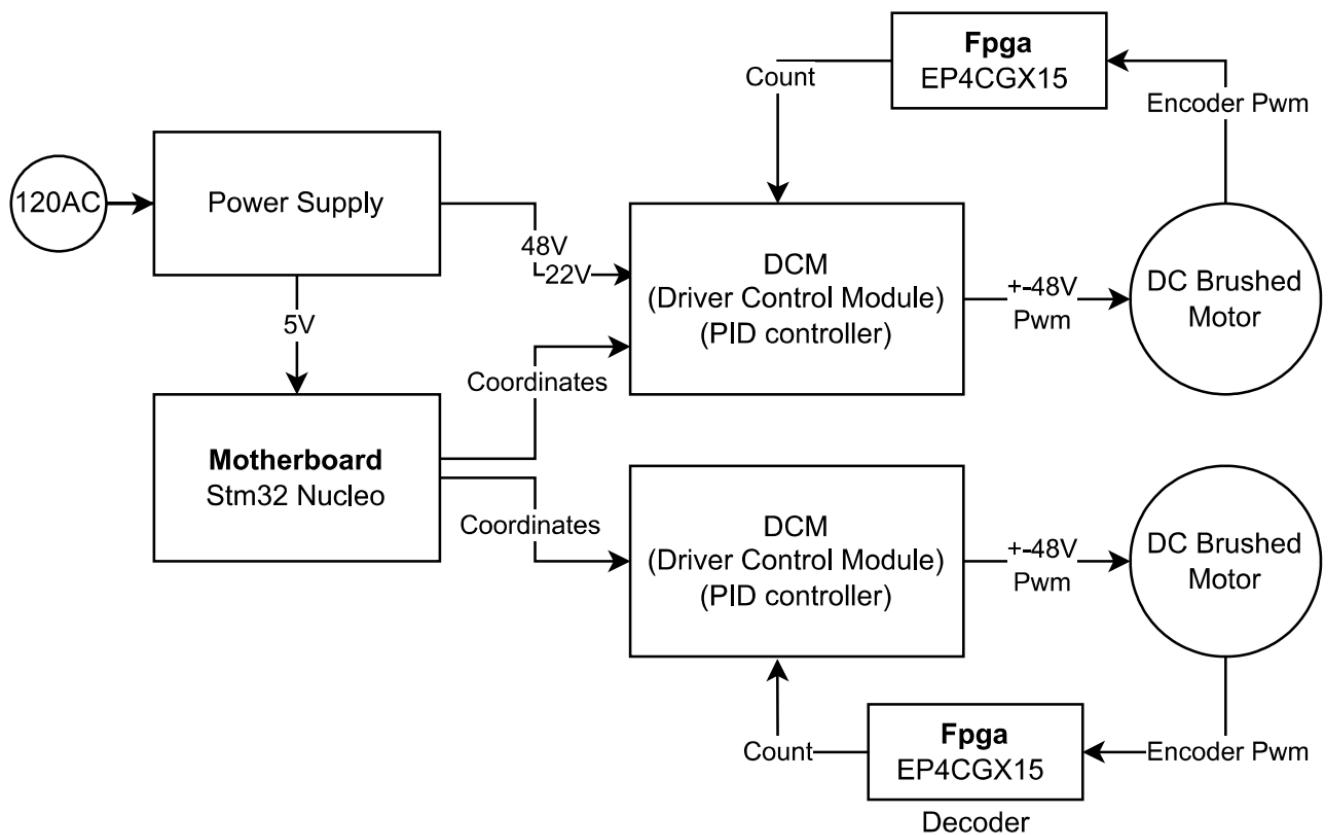


Figure 1.0: Hardware diagram

Acronyms

PSM: Power supply module
DCM : Driver control module
MCU: microcontroller unit
GUI: graphical user interface
RTOS: Real-time operating system
RCG: Requirement Constraints and Goals
USART: universal synchronous and asynchronous receiver-transmitter
PCB: Printed Circuit Board

Motherboard

The motherboard is the brain of the operation. It is where all the heavy computation is performed, such as trajectory planning and homing logic. The requirements are that the motherboard has to physically connect to the robot, receive 5V from the power supply and send the desired position to the driver control module.

MCU selection

The MCU had to satisfy a couple of RCGs. One of the requirements was to have at least 60Kbits of SRAM, to have headroom for matrix multiplication required in the trajectory planning. Also, the clock speed had to be above 16 Mhz to meet the control frequency requirements of the PID controller. Furthermore we had to have more than 6 USART ports to send the desired coordinates to the DCMs for all 4 motors (2 for the Base, 2 for the Elbow, and 1 for Linear Actuator and gripper). For these reasons the chosen MCU was the STM32F4.

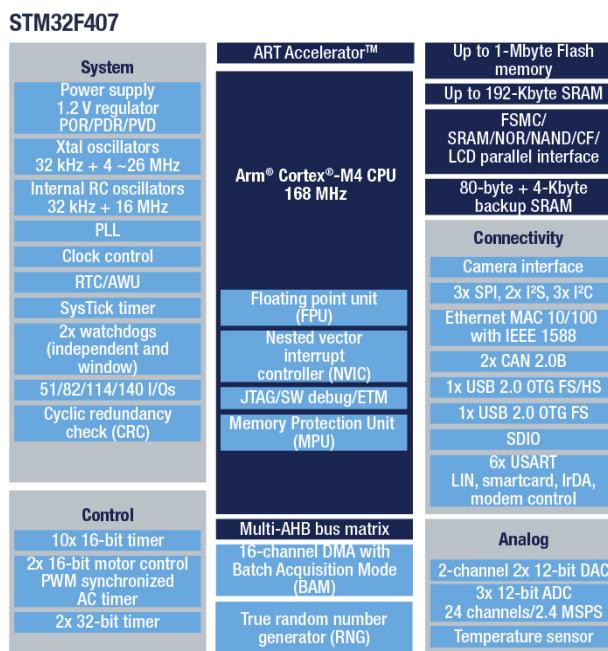


Figure 2.0: STM32L476RG Hardware diagram[1]

The STM32L476RG provides a fast clock speed at 168Mhz and 192kbyte of SRAM, and has 6 USART ports, thus meeting our requirements.

Furthermore, the possibility to run Rtos increases the ability to perform heavy tasks in real time such as path planning and digital filters. And the choice to use HAL with CubeMX helps for fast prototyping and testing.

In this design the motherboard is only composed of the microcontroller board. This was a combined decision with the mech and elec team to increase the safety, facilitate the wiring and increase the modularity of the system. One safety concern is the clearance between the MCU signals and the high voltage delivered by the power supply. With our design we have only one ribbon cable carrying 48V from the power supply to the DCM and another signal ribbon cable from the motherboard to the DCM, giving a higher clearance between the MCU and the high voltage. Another safety concern is the temperature of these boards: if the power supply is mounted together with the other boards the temperature would rise and could damage the electrical system, so we separated the power supply with the proper cooling and used ribbon cables for this high voltage and high current system. Furthermore this design enables for an easy change of motherboard to a more powerful computer able to perform more advanced tasks such as computer vision and/or a GUI.

Power Supply Module

The power supply module is where all the power is delivered for all boards and components.

Circuit

RCGs

Some of the requirements for the circuit were: Convert 120AC to 22DC at 20Amps and 48V at 5 Amps. And we had a constraint of 20 Amps for each transformer.

Linear power supply

Our team opted to design a linear power supply over a switching mode power supply since our team had prior experience with such systems thus increasing the robustness of our design.

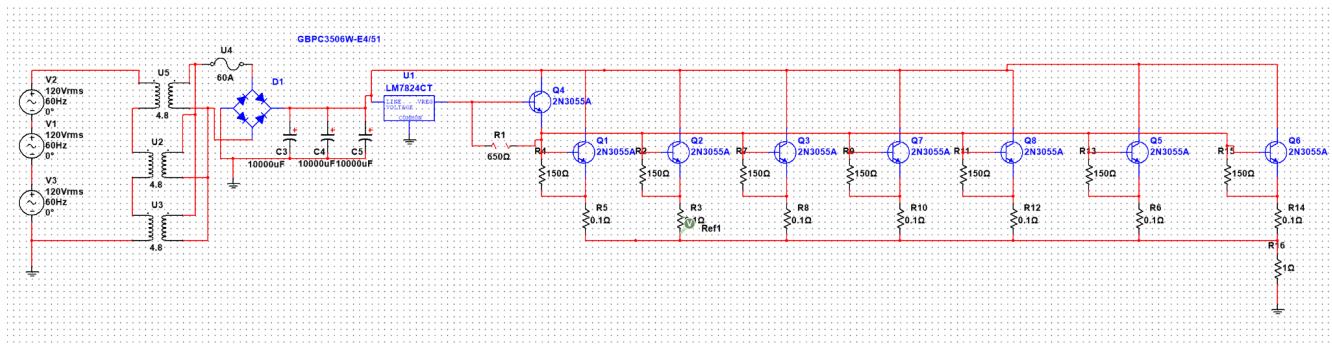


Figure 3.0: Power supply circuit

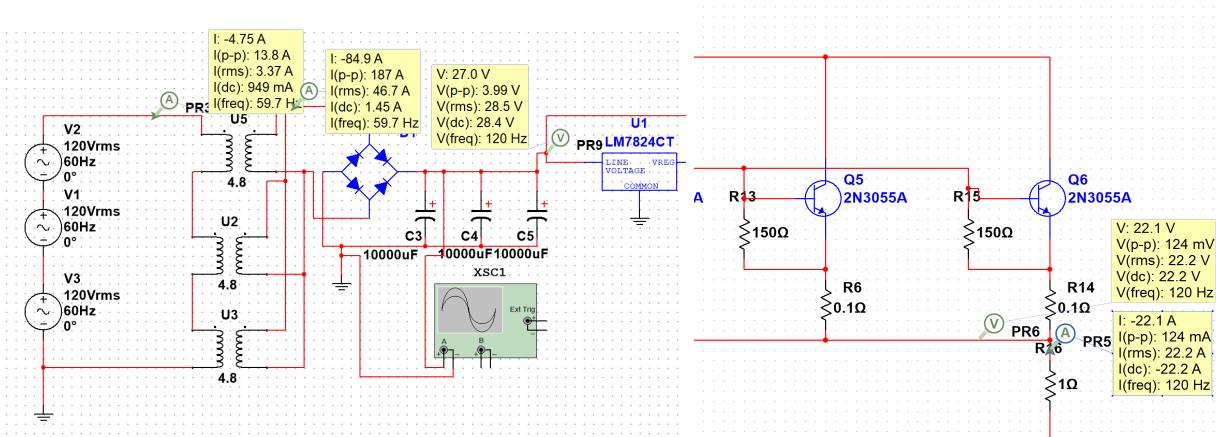


Figure 3.2: Power supply simulation

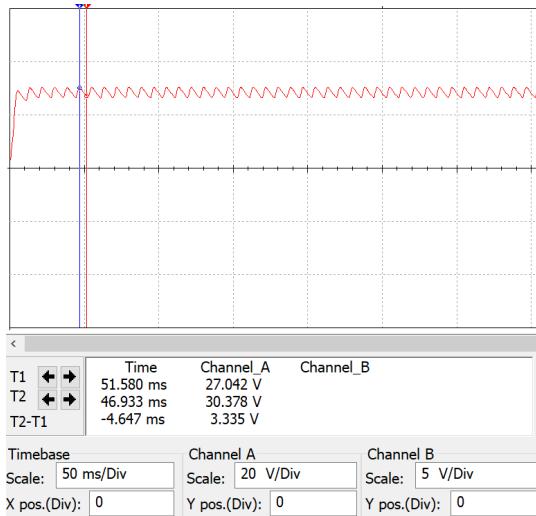


Figure 3.3: Response from oscilloscope

The system is rather simple: it has a 120AC input from the wall plug and which is reduced to 25 Vrms. This voltage goes through a full bridge rectifier and smoothing capacitor to create a DC voltage. Then we used a voltage regulator and 8 BJTs to increase the delivered current up to 25Amps. And as can be seen in figure 3.2 the system successfully delivers 22V at 22A

Boost converter

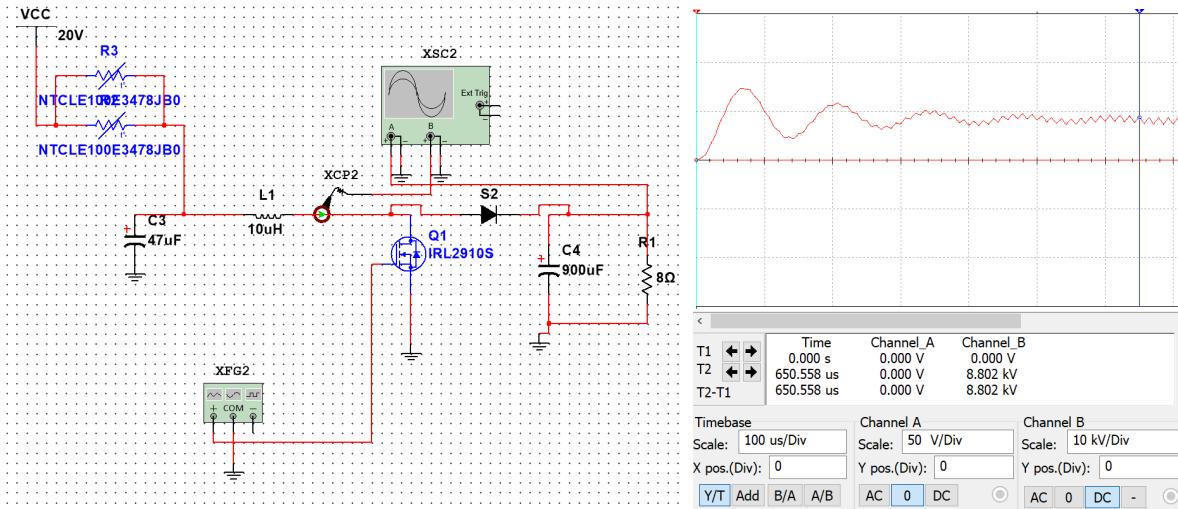


Figure 4.0: Boost converter simulation

In order to convert the 22V to 48V we used a boost converter. Above in figure 4.0 we can see a simulation of the circuit with the function generator inputting a 50% pwm to the mosfet. For protection we used a ntc to prevent the inrush current to go above 15A which could damage the linear power supply.

Although this circuit boosts the voltage successfully it is highly unstable and for this reason we need to control the pwm to prevent that. Using Matlab simulink we recreated the circuit and built a simulation of a PID that outputs the pwm inputted into the mosfet gate and receives a scaled down output voltage as feedback thus successfully boosting the voltage to exactly 48V as can be seen in Figure 4.2 .

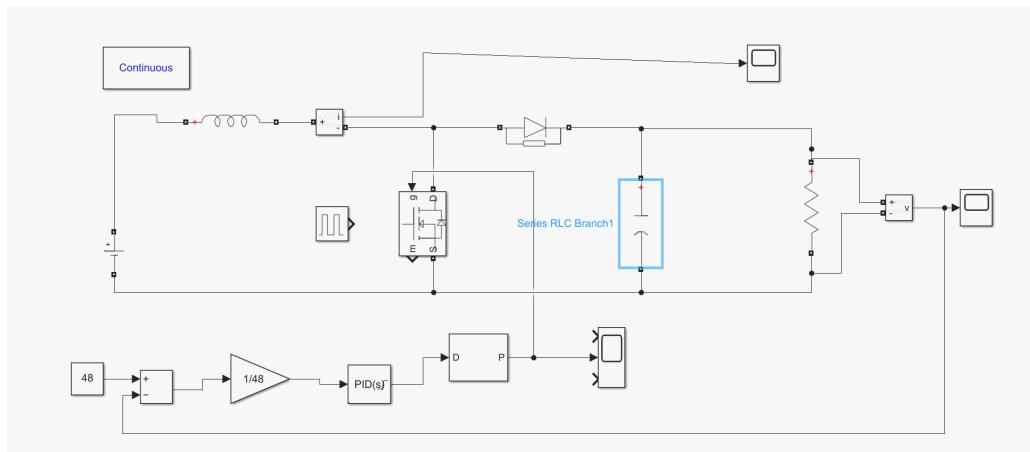


Figure 4.1: Simulink model

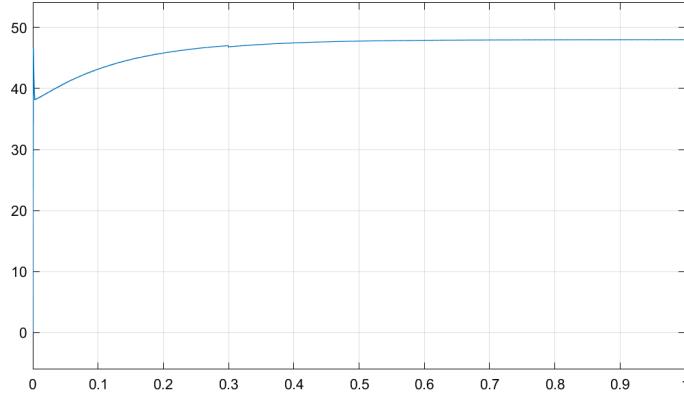


Figure 4.2: Output of simulink model

Component selection

For the linear power supply, we used 3 Hammond 500VA transformers in parallel since each can deliver 25 Vrms at 20 Arms, and through simulation we could determine that the system required about 45Arms. Also, for safety we added a fuse of 60 Amps to prevent overcurrent and the destruction of the transformers.

The chosen full bridge rectifier was the GBJ5010-BP which has a max forward current of 50A and a max forward voltage of 1000V.

The chosen capacitance was calculated to be 30000uF using the following formula:

$$C >= \frac{(I_{max} * T_{discharge})}{(V_{before discharge} - V_{after discharge})} \quad (1)$$

I_{max} is 20A, Voltage before discharge has a maximum of 35V and a minimum of 29V as per Lm7824 datasheet, and $T_{discharge}$ is equal to 1/60hz giving $C >= 20,750\mu F$, for a more stable response we choose 30,000uF capacitance.

Then to regulate the voltage we choose the Lm7824 but since the max current of the voltage regulator is 1Amp we added 8 BJTs to increase the output current up to 25A. One important component that we had to choose carefully was the 0.1 Ohm resistor , which has to have a maximum power rated as above 2.5W since each consumes a max of 5A.

For the boost converter we used the following formula to calculate the inductance and capacitance

$$L > \frac{D * V_{in} * (1 - D)}{(freq * 2 * I_{out})}; D = 1 - \frac{V_o}{V_i} \quad (2)$$

$$Cap > \frac{I_{out}}{(V_{ripple} * freq)} [4] \quad (3)$$

Thus for a pwm frequency of 70Khz, a lout equal to 5 Amps and a Vripple of 0.1V we get C>714uF and L>7.8uH.

PCB

RCGs

The power supply PCB has to be small enough to fit in the case developed by the mech team. Thus we had a constraint of a max area of 300mm². And the temperature could not exceed 50 degrees Celsius. Another constraint was the PCB minimum trace width. This can be calculated with the formulas below:

$$Area[mils^2] = (Current[Amps]/(k * (TempRise[deg.C^0])^{0.44}))^{(1/0.725)} \quad (4)$$

$$Width[mils] = Area[mils^2]/(Thickness[oz] * 1.378[mils/oz]) \quad (5)$$

Formula 3.0: Minimum trace width

Thus with a maximum current as 20A, the maximum temperature rise as 40degrees, the thickness as 4oz and k=0.048 as per IPC-2221 for external layers gives us a minimum width of 2.07mm.

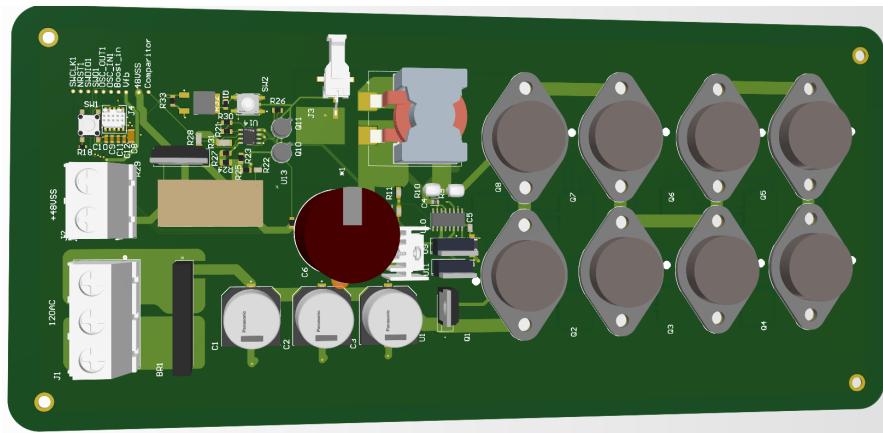


Figure 5.1: Top 3d View

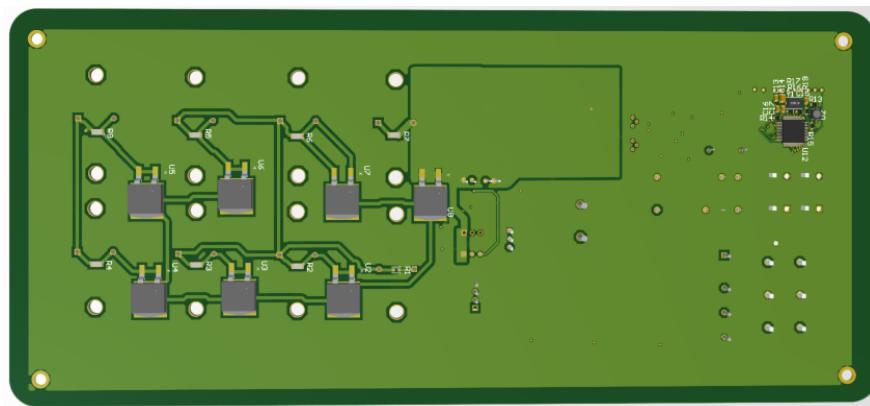


Figure 5.2: Bottom 3d view of the pcb

The width constraint was achieved by using the rules on Altium designer as shown below, which constraints the width for a minimum of 2.08mm for high current nets. Also we added a high voltage clearance recommended as per IPC-2221 of 0.83mm for 48V. Furthermore the board size does not exceed 200mm² thus achieving all our requirements.

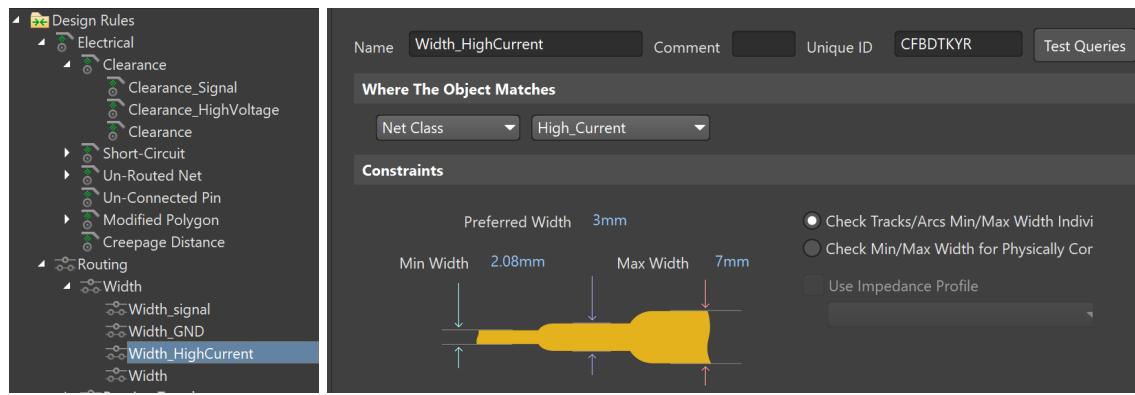


Figure 5.3: PSM Design rules

Organization

In order to optimize the space a multilayer board was chosen with the middle layers with 1oz thickness to trace signals and small current nets. Furthermore, all the resistors and capacitors were chosen to be above 0805 package since smaller than those are really hard to stuff in the PCB.

The components were aligned and grouped as the circuit was designed. As you can be seen on the layers on Appendix A or in figure 5.1 we have the input in one end of the board and closeby we have the full bridge rectifier and the smoothing capacitors, on the right side of the board we dedicated to add the BJTs and at last at the left top of the board we have the overcurrent protection and the microcontroller.

The connectors were chosen to be able to withstand the high current and also fit 8 gauge wires. Furthermore the mounting holes were grounded and are fit for m4 screws that will attach to a heat sink for heat dissipation.

The design also includes multiple labeled testing points for debugging purposes and 1 switch to simulate the overcurrent and another to reset the MCU.

For more information such as silk screen, traces and bill of material, refer to appendix B where assembly drawings, schematic prints and the used components part numbers can be found.

Driver Control Module

The driver control module receives the coordinates signal from the motherboard and the count from the FPGA. With that it controls the speed and position of the motor using a PID controller and thus achieving the desired position.

Circuit

RCGs

The DCM needs to output a 48V pwm to the motor and also must be able to rotate both ways. The motor cannot exceed 5Amps and the goal is to reduce the inrush current as much as possible.

Hbridge

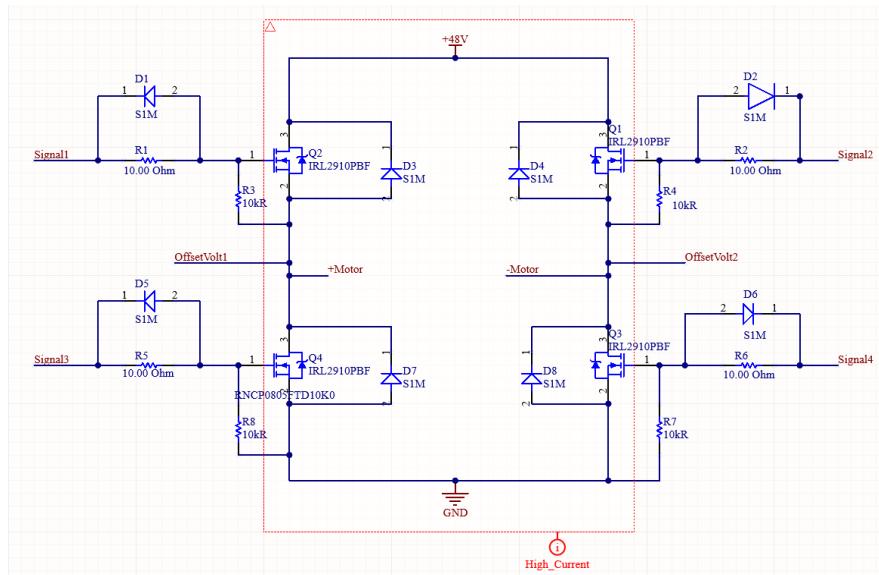


Figure 6.0: H Bridge

The HBridge is the main part of the Driver control module and where the current and voltage is delivered to the motor inputs. As can be seen in figure 6.0 we are using exclusively IRL2910 N-mosfets. This power mosfet was carefully chosen since it has a max continuous drain current of 48Amps and a maximum drain to source voltage V_{ds} of 100V which is way more than we need and complies with all our requirements and constraints. The 10k resistors were added to drain the gate voltage and increase the switching speed of the mosfets. Furthermore, for safety reasons we also added flyback diodes to prevent overcurrent at the drain of the mosfet.

These input signals (Signal 1,2,3,4) come from the gate drivers described in the next section.

Gate drivers

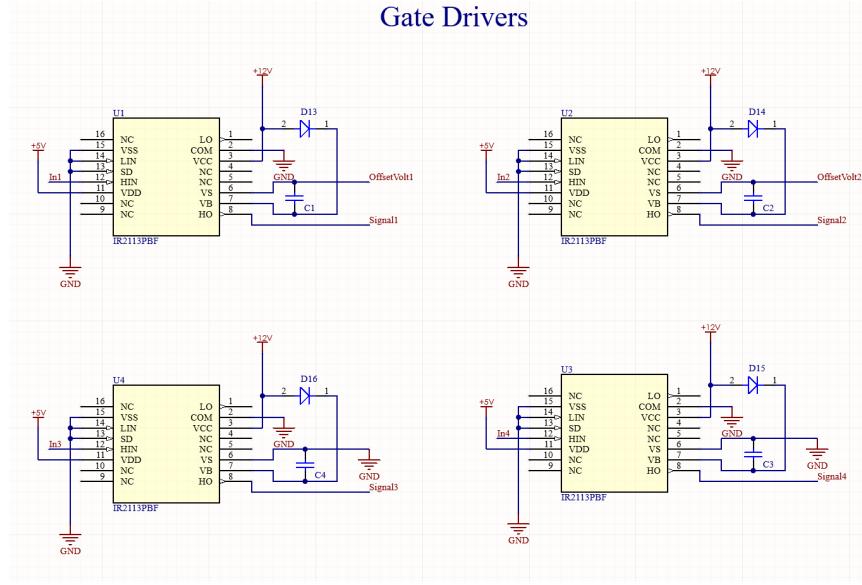


Figure 6.1: Gate driver ICs

4 gate drivers were used to send the pwm signals from the microcontroller to the power mosfets. With a 10Ohms resistor gate current can go up to $60V/10Ohms = 6Amps$, which the microcontrollers cannot handle. Thus a gate drivers are incredibly helpful in those situations to produce enough high current to drive the gate of the power mosfet.

Optocouplers

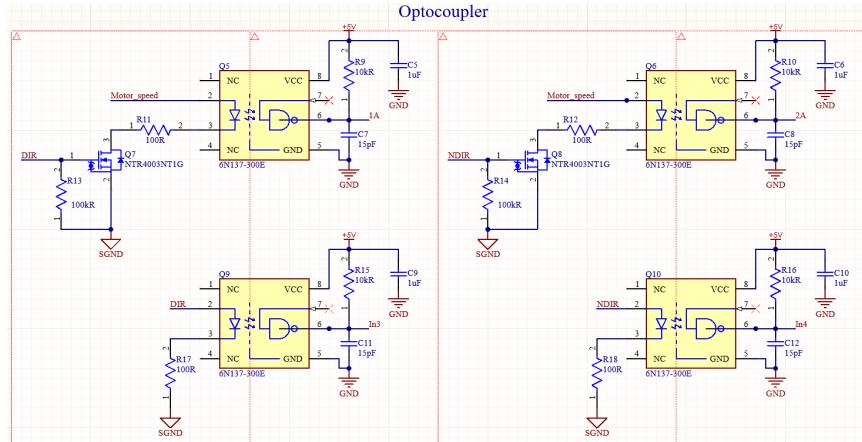


Figure 6.2: Optocouplers

Finally for safety purposes, optocouplers were used to connect the high Voltage circuit and the microcontroller, separating the grounds and reducing noise to the pwm signal.

Simulation

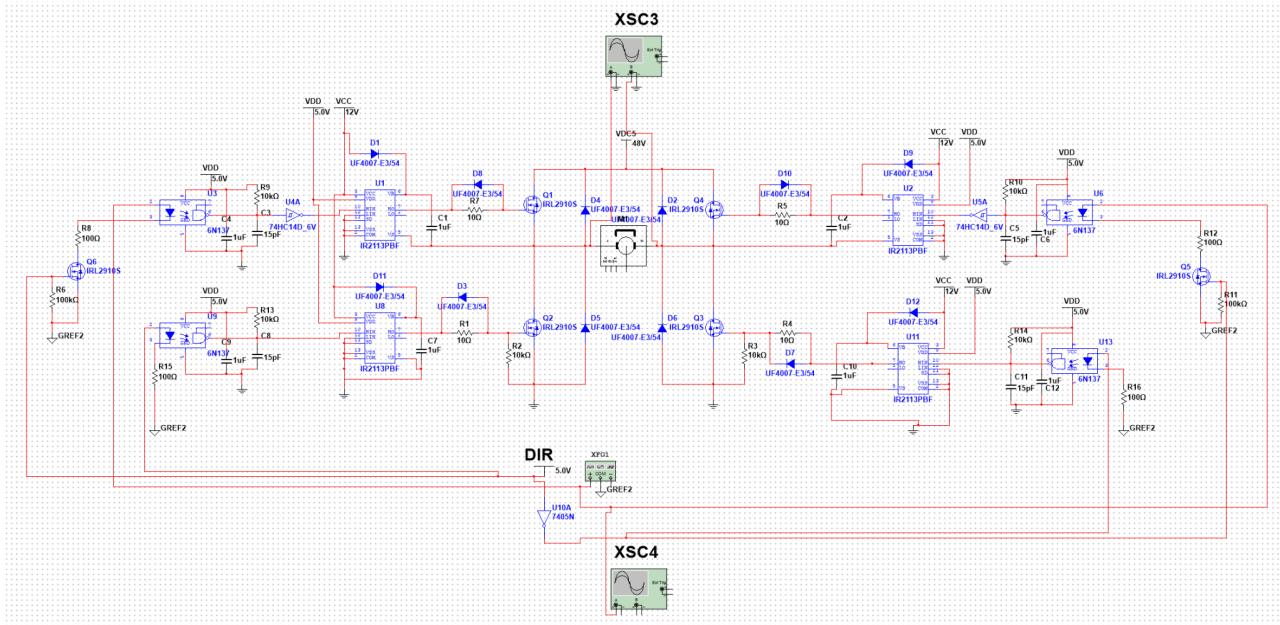


Figure 7.0: Full Driver Control Module circuit simulation

As can be seen in figure 7.0 we simulated the Hbridge integrated with the gate driver ic and the optocouplers.

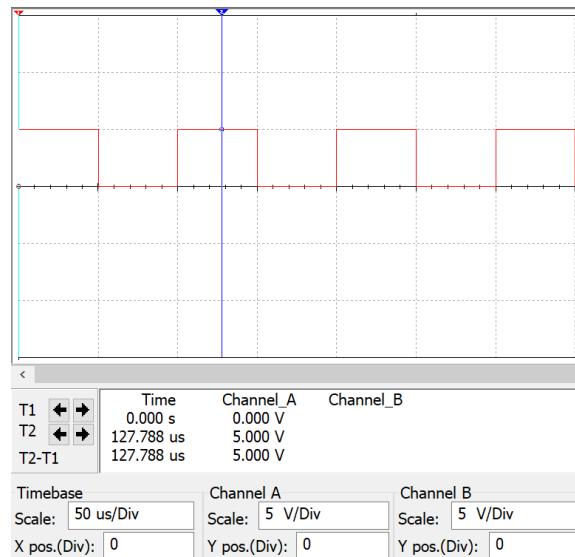
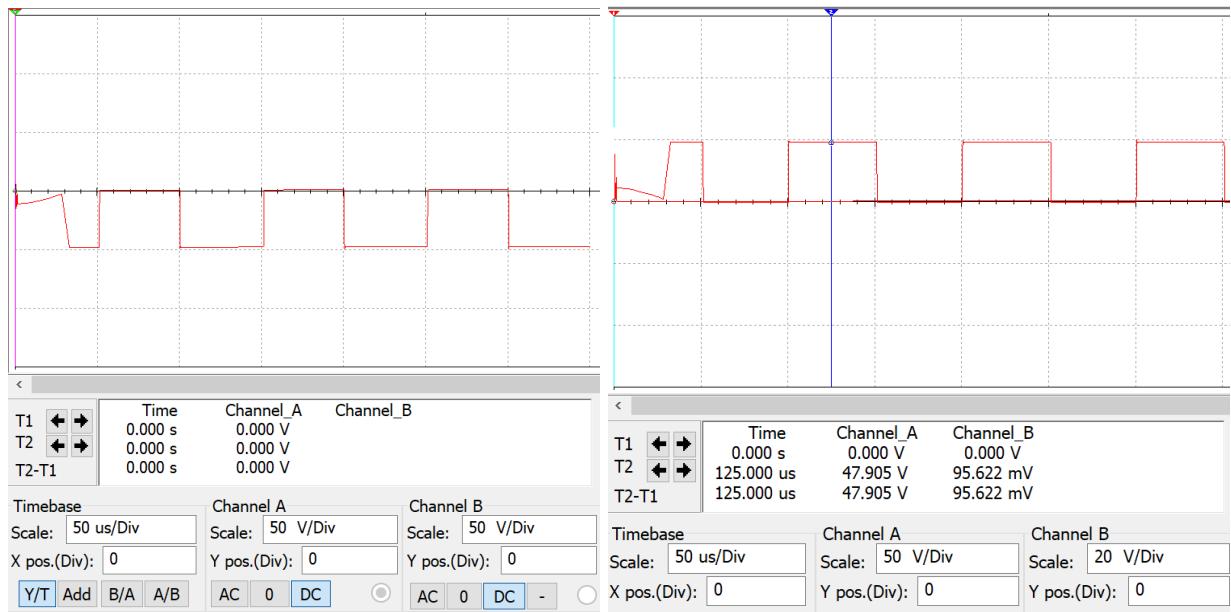


Figure 8.0: Function generated pwm at 10khz (XSC4 Output)



As can be seen in Figure 8.0 we are inputting a 10kHz pwm into the hbridge and depending on the direction signal we get the output from figure 8.1 which spins the motor clockwise or we get the output from figure 8.2 which spins the motor counterclockwise.

PCB

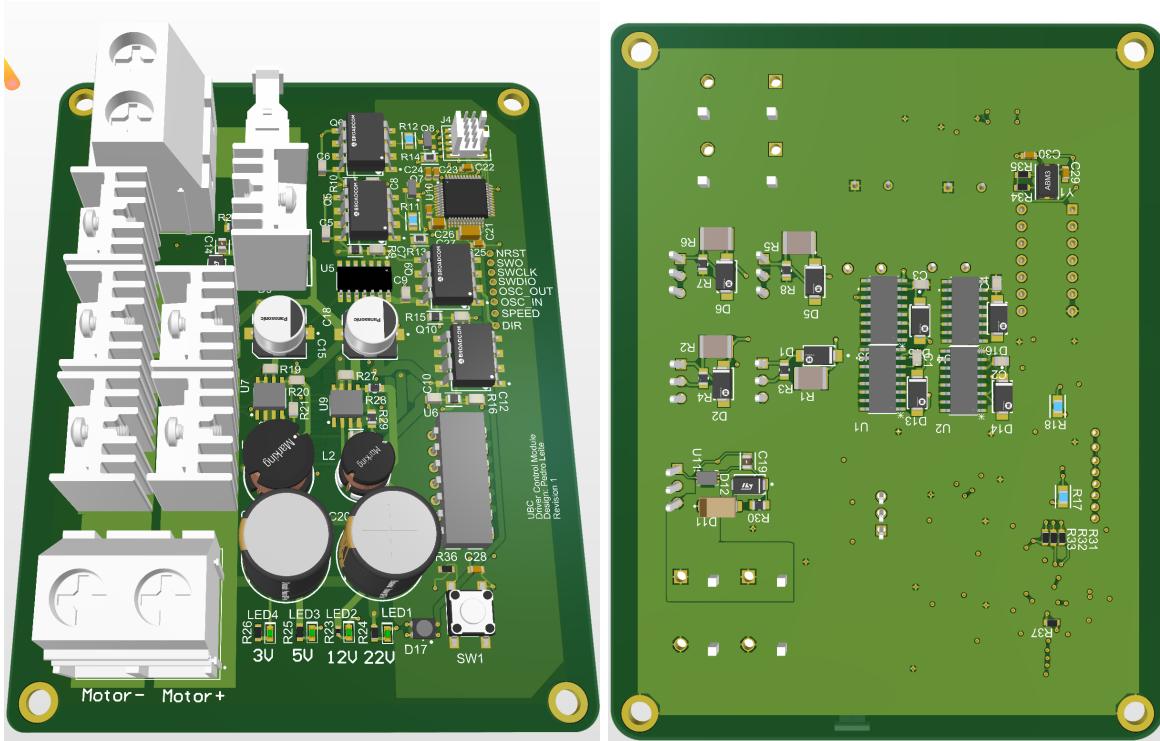


Figure 9.0: 3d view of the DCM PCB

RCGs

The DCM PCB has to be small enough to fit in the base. Thus we had a constraint of a max area of 100mm^2 . Another constraint was the PCB minimum trace width. This could be calculated using the same formula as in (5). Thus the traces must not exceed 1.1mm and must have a clearance of minimum of 0.87mm. Again, these requirements were met by using the rules in altium which helps to ensure that these requirements are met.

Organization

Again we used a multilayer board to optimize for space and did not exceed 0805 for the same reasons. The connectors chosen were the same as the power supply board since it meets all the requirements for voltage, current and wire gauge.

We added a heat sink for each mosfet to dissipate the high current going through them which can damage if it gets too high.

For more information such as silk screen, traces and bill of material, refer to appendix B where assembly drawings, schematic prints and the used components part numbers can be found.

Sensor

Fpga selection

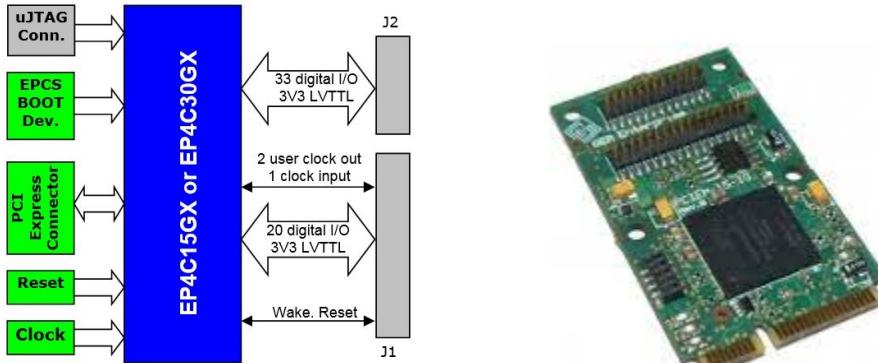


Figure 10.0: EP4CGX15 Fpga[2]

The selected FPGA was the EP4CGX15 Fpga with a 53 I/O pins card. This is a relatively simple FPGA but it has a good amount of I/O pins to connect with the multiple encoders of the robot and it is enough for our application.

Quadrature decoder

In order to get the position information from the encoder we need to decode the signals using a FPGA. For this reason we designed a state machine using system verilog that will be loaded to the fpga and sent to the stm32 as a count, which will then be converted to an angle.

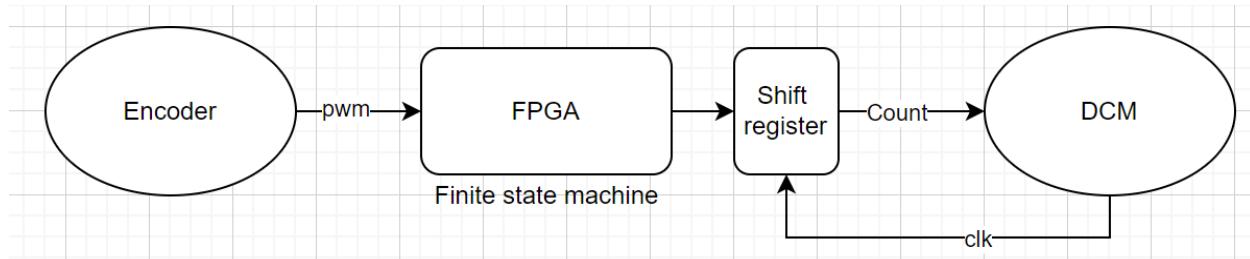


Figure 11.0: Quadrature decoder system architecture

Finite State Machine

The finite state machine has to receive 2 pwms from the encoder and depending on the direction we will increase or decrease the count output.

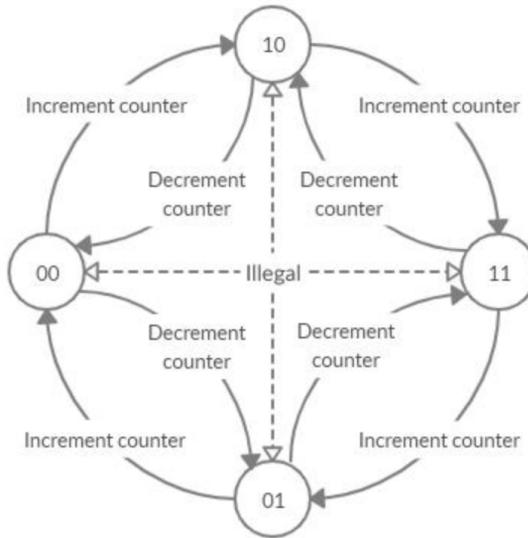


Figure 12.0: Finite state machine diagram[5]

Using verilog we can implement the State machine shown in figure 12.0. Thankfully the state machine is simple due to the nature of the A&B inputs which can only have 2 possible paths at a time. After implementing the code we get the following waveform:

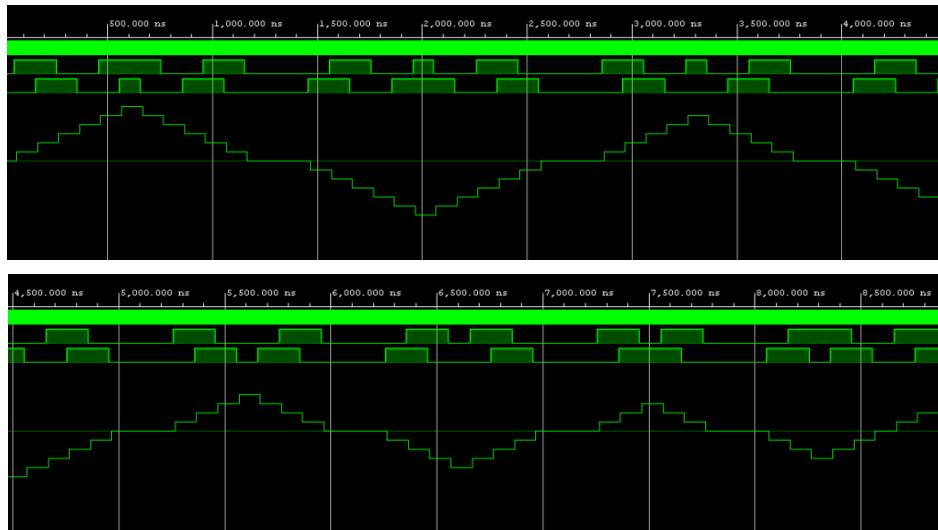


Figure 13.0: Finite State machine testbench with all possible outputs

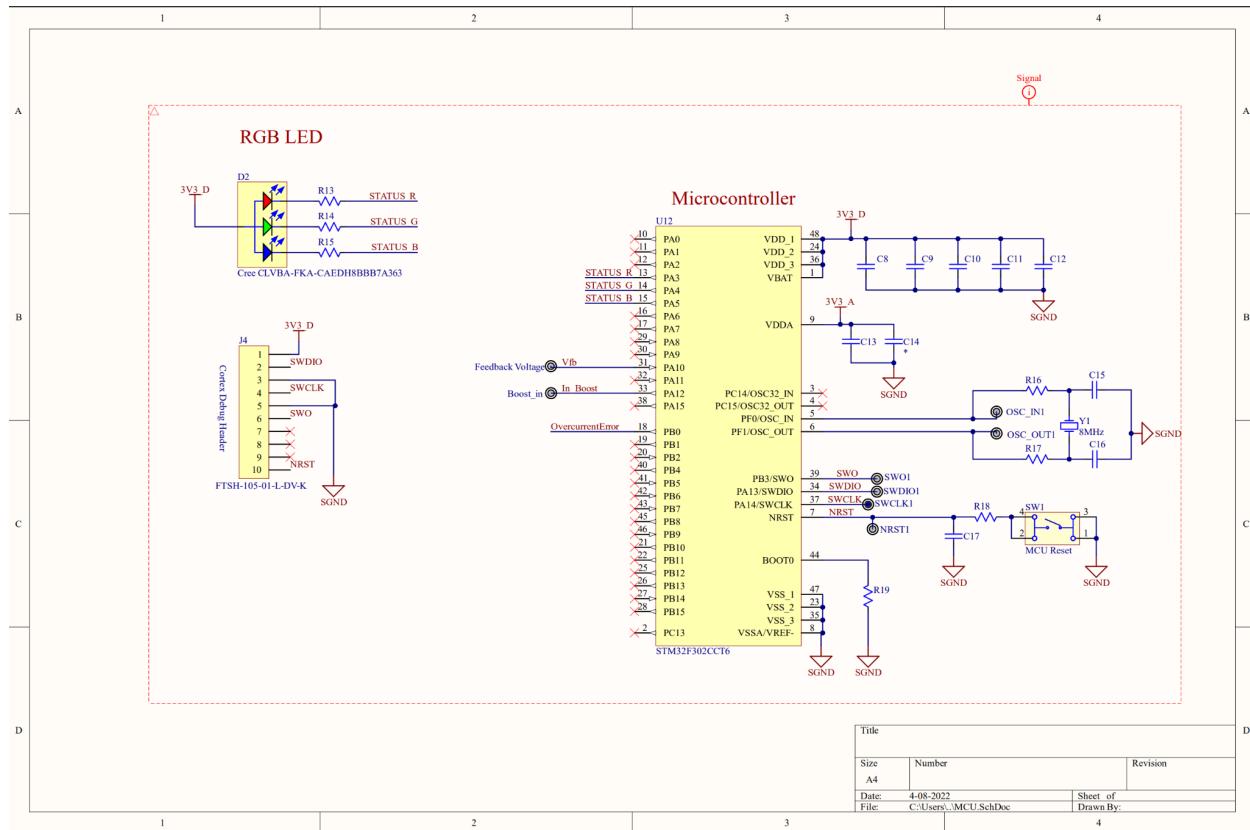
As can be seen in figure 13.0 the finite state machine is responding as intended and the count goes up and down. (for the full code implementation please look into appendix C)
One caveat of our design that can't be seen in the waveform is that the count starts at 500 and goes up to 1000, that is because we wanted to avoid negative numbers. Thus since our encoder has 500 possible positions it can go from 0 to 1000, with 0 being -180° and 1000 being 180°.
After that we send the output from the decoder to a shift register and the microcontroller will send a stream of 9 clock cycles to retrieve the whole output from the shift register.

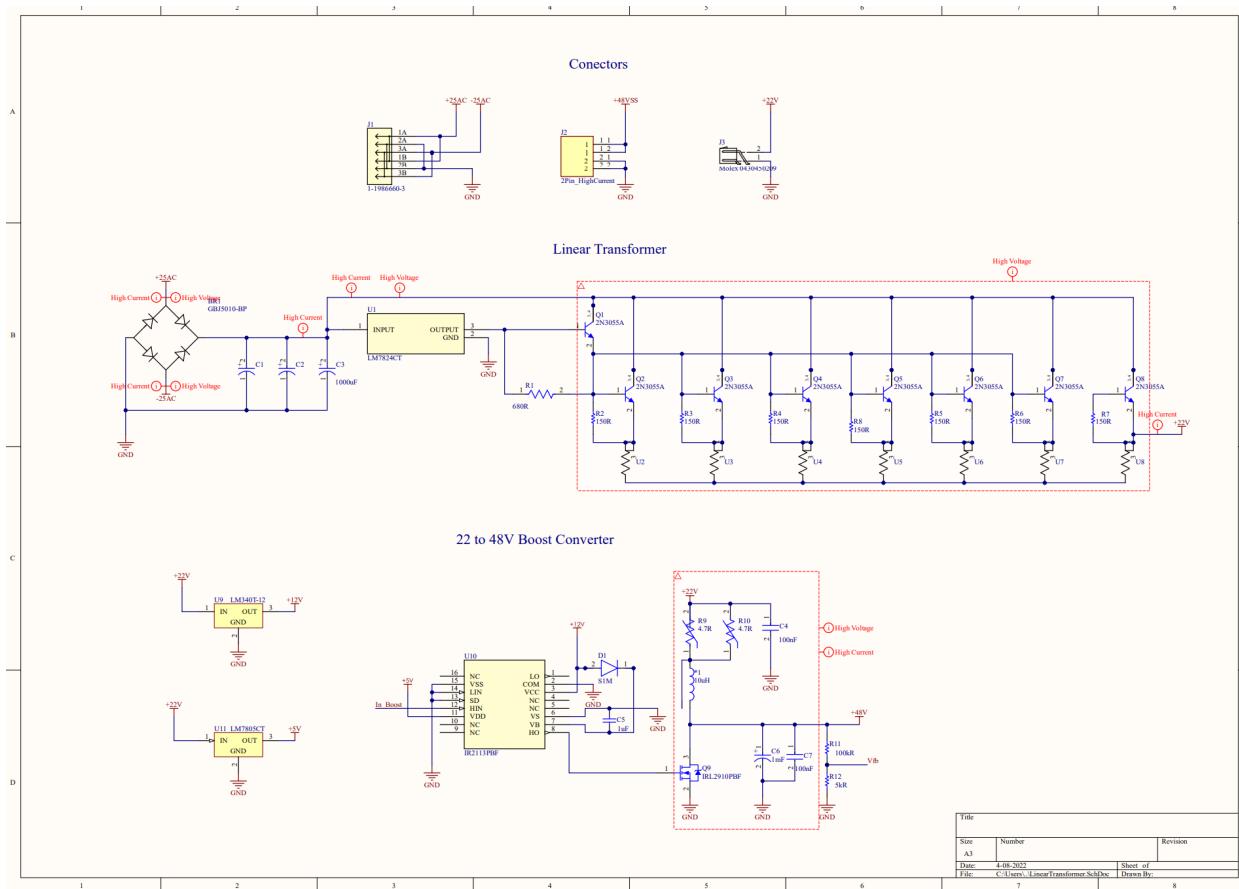
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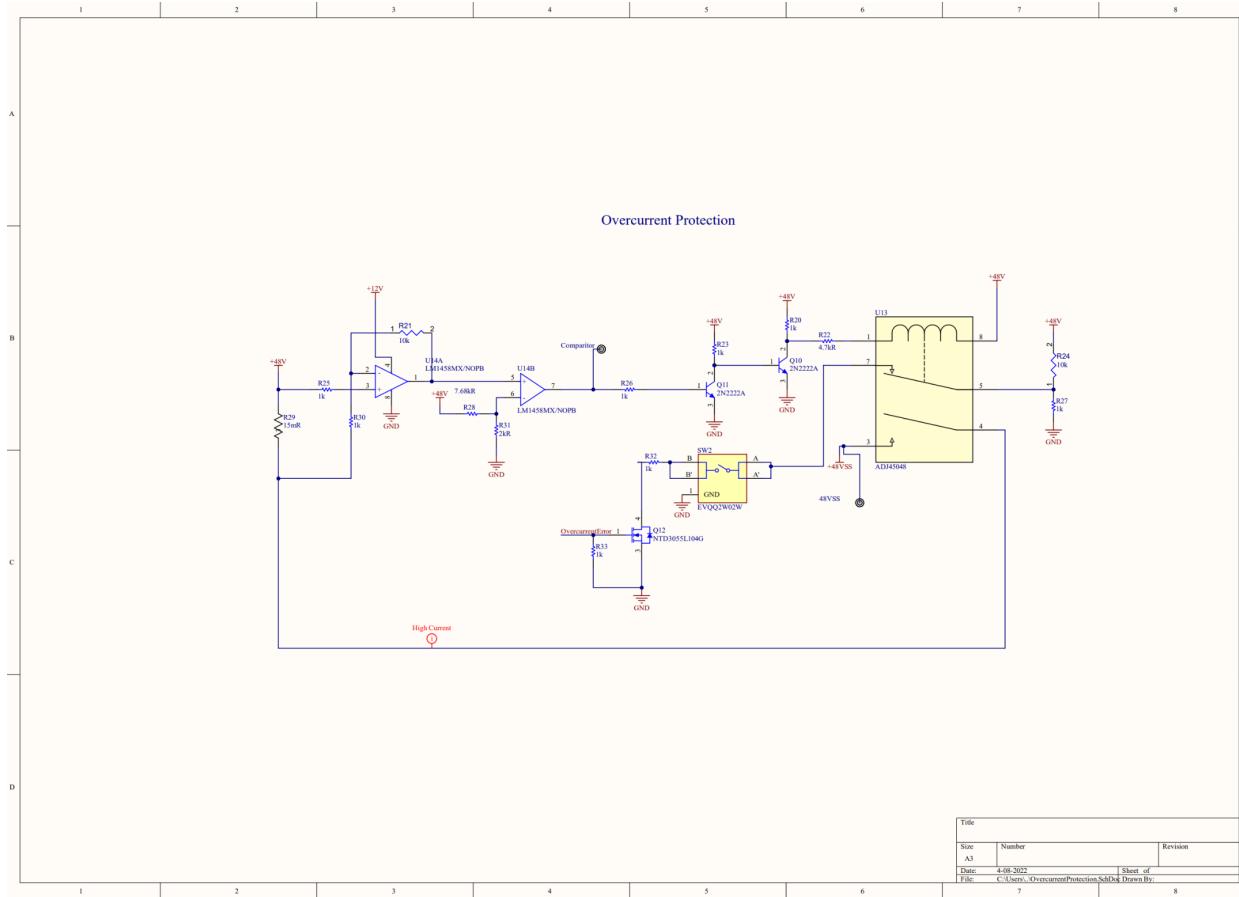
- [1] <https://www.st.com/en/microcontrollers-microprocessors/stm32f407zg.html>
- [2] https://marketplace.intel.com/s/offering/a5b3b0000004c57AAA/mini-pcie-fpga-card-with-53-io-and-ep4cgx15-fpga?language=en_US
- [3] <https://www.7pcb.com/trace-width-calculator.php>
- [4] <https://learn.adafruit.com/diy-boost-calc/the-calculator>
- [5] https://www.researchgate.net/figure/a-State-machine-based-quadrature-decoding-algorithm-and-b-modified_fig2_3091172

APPENDIX A

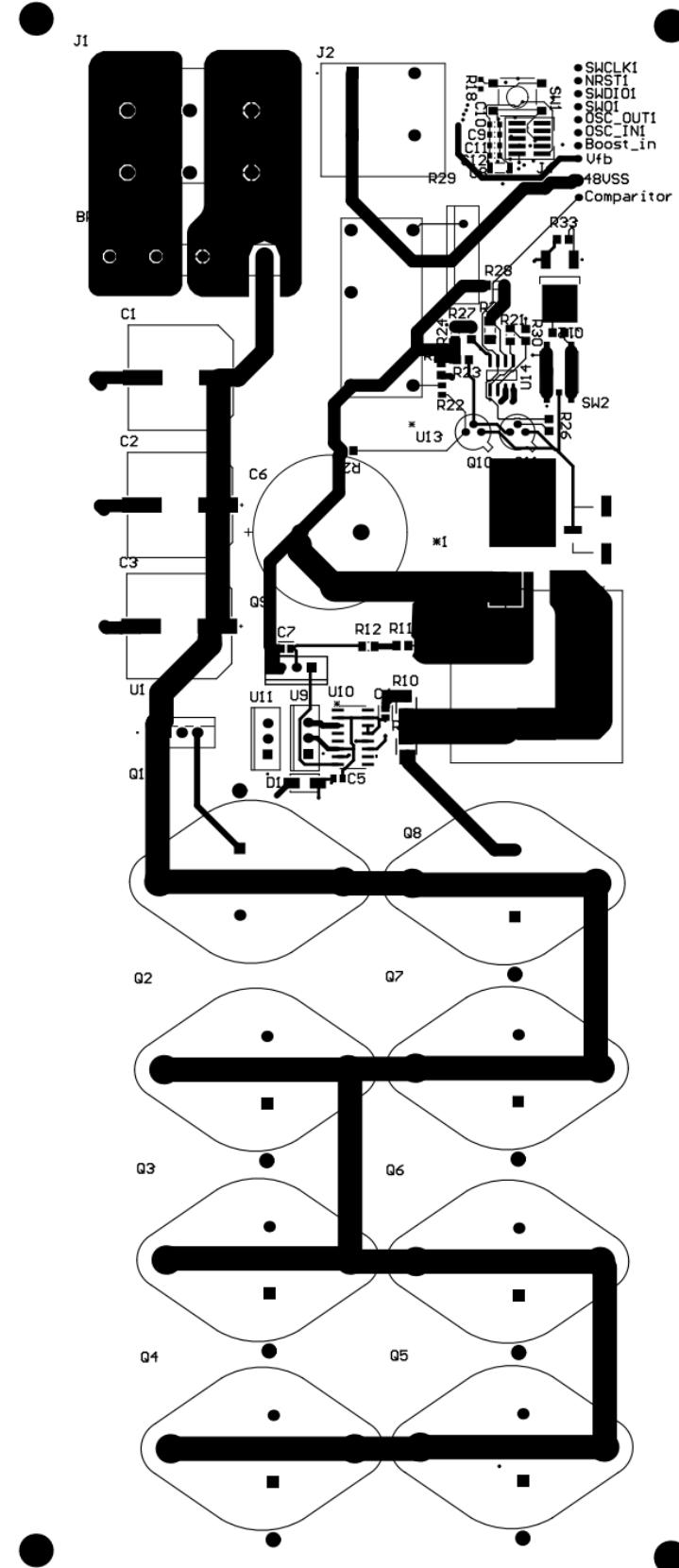
POWER supply



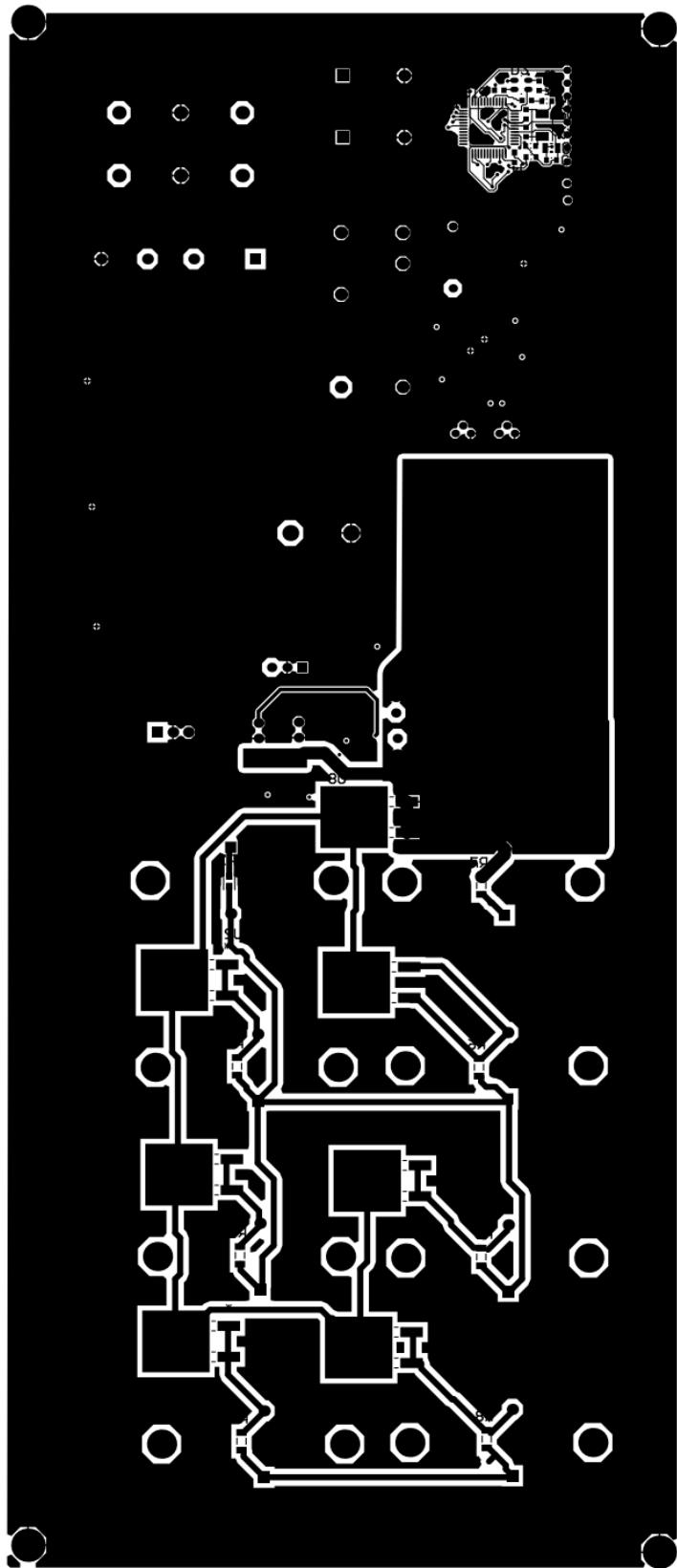




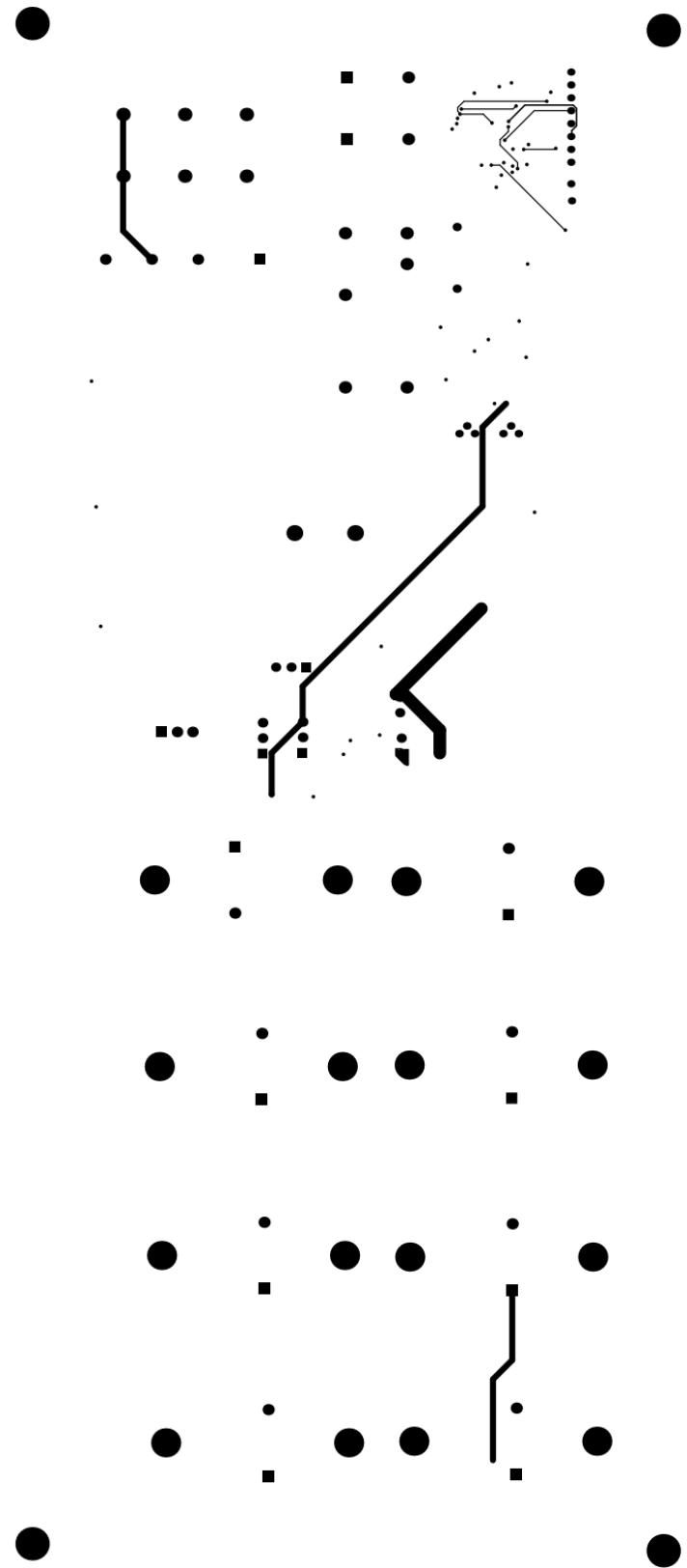
Top Layer



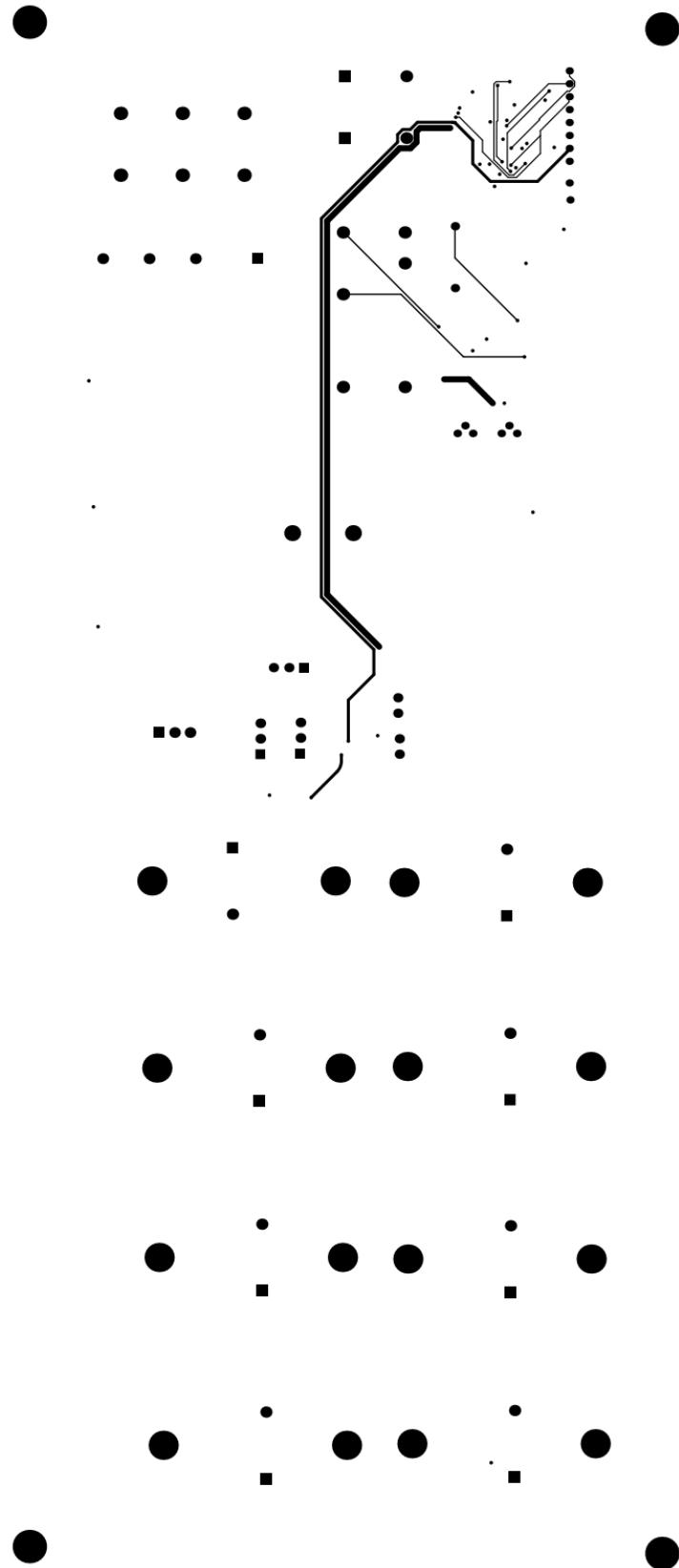
Bottom Layer



Signal Layer 2



Signal Layer 2



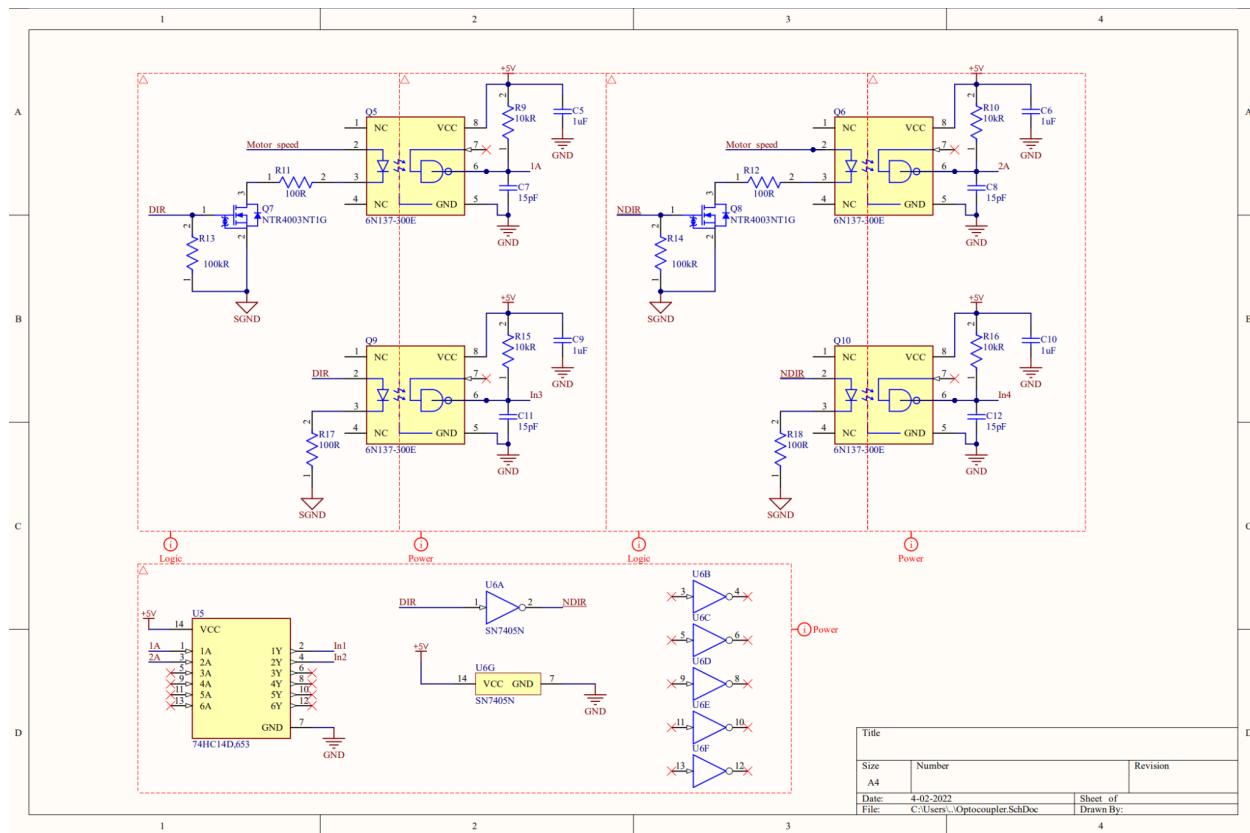
Bill Of materials

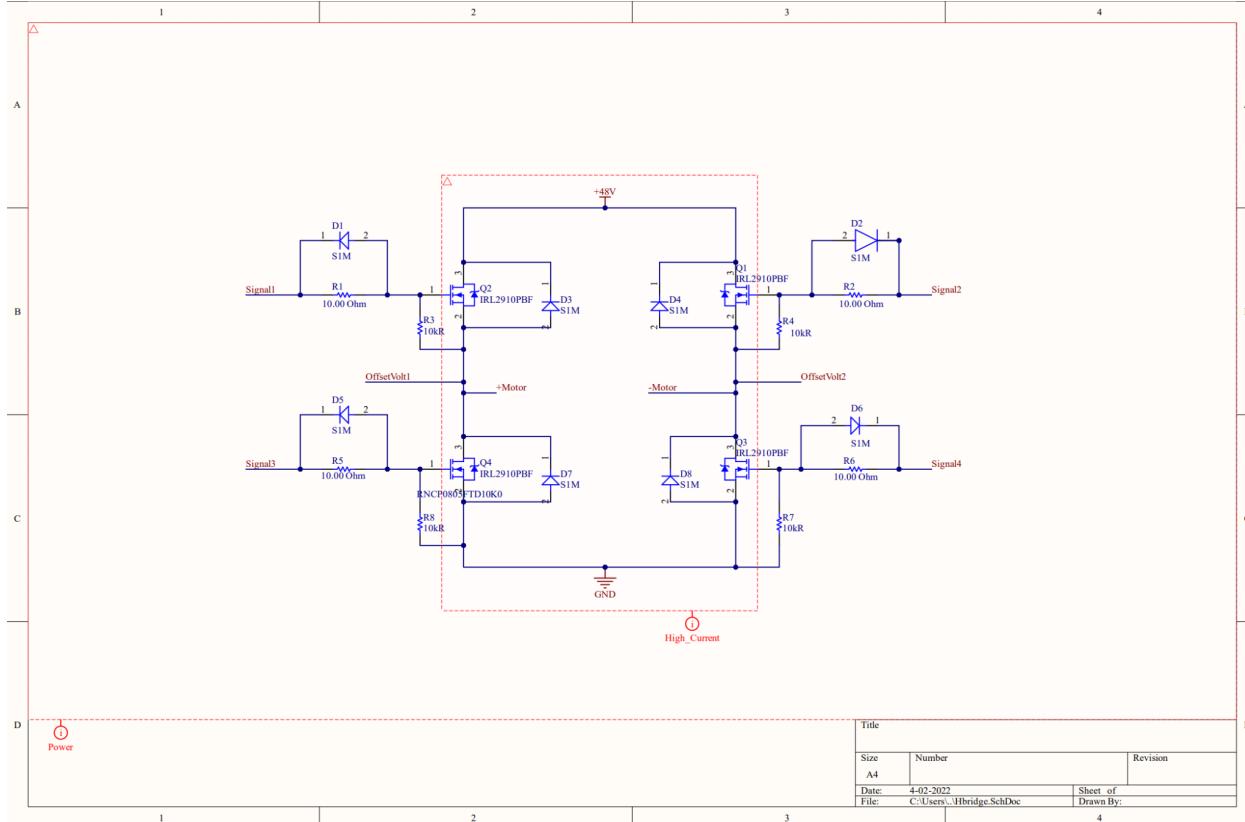
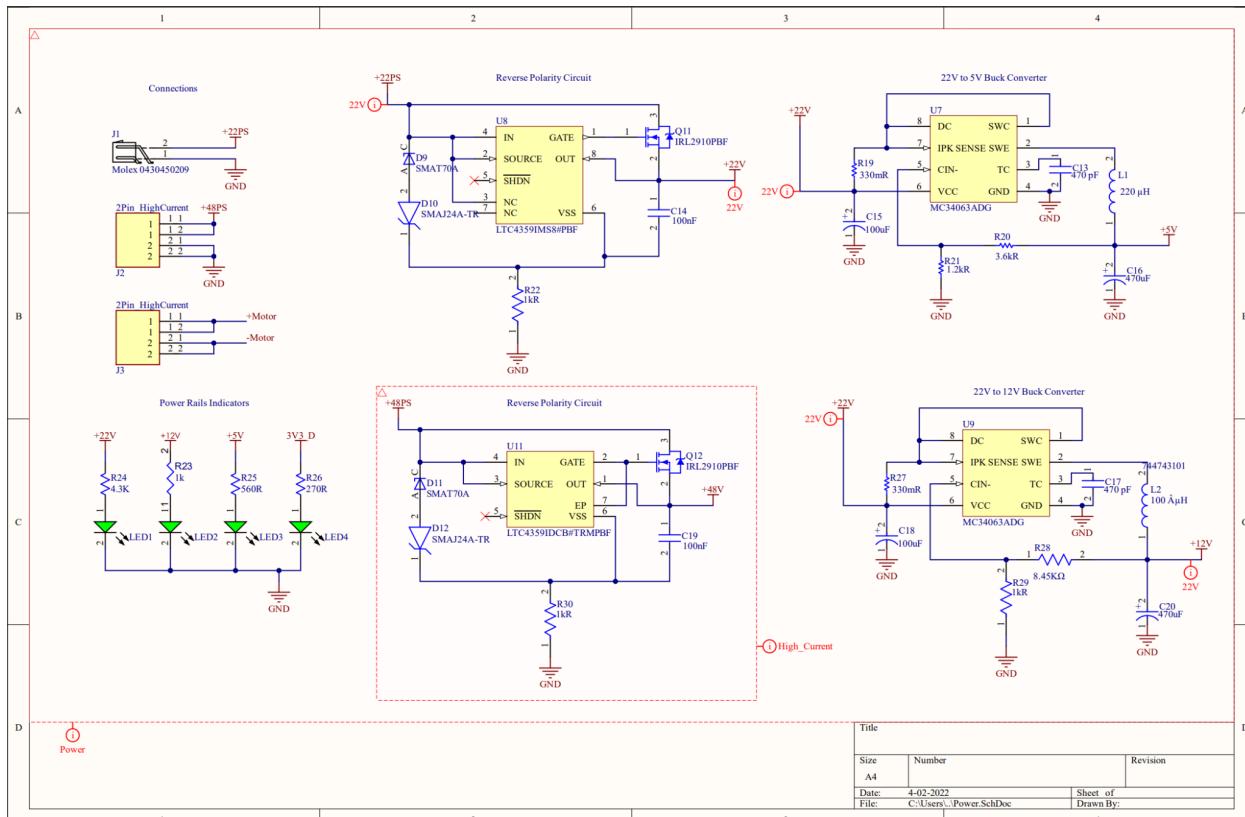
Comment Description	Designator	Footprint	LibRef	Quantity
"Inductor_10uH" "Inductor Power Shielded Wirewound 10uH 10% 100KHz Ferrite 28A 0.0025Ohm DCR Automotive Tray"				
"*1" "IND_PQ2617" "Inductor_10uH" "1"				
"Thru-Hole Test Point" "" "48VSS, Boost_in, Comparitor, Feedback Voltage, NRST1, OSC_IN1, OSC_OUT1, SWCLK1, SWDIO1, SWO1" "TESTPOINT" "CMP-020-0001-1" "10"				
"GBJ5010-BP" "GBJ5010 Series 1.1 V 50 A Through Hole Glass Passivated Bridge Rectifier - GBJ" "BR1"				
"GBJ_MCC" "GBJ5010-BP" "1"				
"EEV-FK1H102M" "CAP ALUM 1000uF 20% 50V SMD" "C1, C2, C3" "FP-FK-J16-MFG" "CMP-05427-000011-1"				
"3"				
"CL21B104KACNNNC" "CL21 Series 0805 100nF 25V ±10% Tolerance X7R Multilayer Ceramic Chip Capacitor" "C4, C7"				
"FP-CL21-IPC_C" "CMP-13271-002854-1" "2"				
"GRM21BR71H105KA12L" "" "C5" "CAPC2013X135X45LL10T25" "CMP-1036-04761-2" "1"				
"LGG2P102MELA45" "105degC Ultra Smaller-Sized Snap-in Terminal Type, 1000 μ F, 220 V, -40 to 105°C, RoHS"				
"C6" "CAP_A45_NCH" "Cap1000uF" "1"				
"1206" "" "C8" "1206 CAPACITOR (TDK C-SERIES)" "1206 Ceramic Capacitor" "1"				
"0603" "" "C9, C10, C11, C12, C13, C15, C16, C17" "0603 CAPACITOR (TDK C-SERIES)" "0603 Ceramic Capacitor" "8"				
"0805" "" "C14" "0805 CAPACITOR (TDK C-SERIES)" "0805 Ceramic Capacitor" "1"				
"S1M" "DIODE GEN PURP 1KV 1A SMA" "D1" "FP-403AE-MFG" "CMP-2000-04942-3" "1"				
"Cree CLVBA-FKA-CAEDH8BBB7A363" "RGB LED" "D2" "Cree CLVBA-FKA-Series (4-SOJ)" "Cree CLVBA-FKA-CAEDH8BBB7A363" "1"				
"1-1986660-3" "No Description Available" "J1" "CONN3_1-1986660-3_TEC" "1-1986660-3" "1"				
"2Pin_HighCurrent" "2 Posn Power Connector, Black, 10.16mm, 1-1986660-" "J2" "TE_1-1986660-2" "2Pin_HighCurrent" "1"				
"Molex 0430450209" "CONN HEADER SMD R/A 2POS" "J3" "Molex 0430450209"				
"CMP-029-000006-1" "1"				
"FTSH-105-01-L-DV-K" "10-Pin 1.27mm Shrouded Cortex Debug Connector" "J4" "Samtec FTSH-105-01-L-DV-K" "1"				
"2N3055A" "Complementary Silicon High-Power Transistor, 3-Pin TO-204, Tray" "Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8"				
"ONSC-TO-204-3-1-07" "CMP-1048-01046-1" "8"				
"IRL2910PBF" "N-Channel 100 V 55A (Tc) 200W (Tc) Through Hole TO-220AB" "Q9" "IRL2910""IRL2910PBF" "1"				
"2N2222A" "High Speed Switch, 0.6 A IC, -65 to 175 degC, 3-Pin TO-18, RoHS, Bulk" "Q10, Q11"				
"STM-TO-18-3" "CMP-2000-05381-1" "2"				
"NTD3055L104G" "Power MOSFET, 12 A, 60 V, Logic Level, N-Channel, 3-Pin DPAK, Pb-Free, Tube" "Q12"				
"ONSC-DPAK-3-369C-01_V" "CMP-1058-00384-1" "1"				
"CRCW0603680RFKEAHP" "RES Thick Film, 6800, 1%, 0.33W, 100ppm/°C, 0603" "R1"				
"FP-CRCW0603-HPe3-IPC_A" "CMP-02407-004503-1" "1"				
"CRCW1206150RFKEA" "" "R2, R3, R4, R5, R6, R7, R8" "RESC3216X60X45NL10T20" "CMP-2003-01812-1" "7"				
"NTC4.7Ohms" "Thermistor NTC 4.7 Ohm 5% 2-Pin Radial 2880K < -5 Bulk" "R9, R10" "NTCLE100E3478JB0"				
"NTC4.7Ohms" "2"				
"ERJ-6ENF1003V" "" "R11" "RESC2013X70X40ML20T20" "CMP-2001-04377-1" "1"				
"CRCW08055K00FKTA" "" "R12" "RESC2013X50X30ML20T20" "CMP-2001-04239-1" "1"				
"0603" "" "R13, R14, R15, R16, R17, R18, R19" "0603 RESISTOR (YAGEO)" "0603 Resistor" "7"				
"Resistor 1k +/-1% 0805 125 mW" "Chip Resistor, 1 KOhm, +/- 1%, 0.125 W, -55 to 155 degC, 0805 (2013 Metric)" "R20, R23, R25, R26, R27, R30, R32, R33" "RESC2013X70X40ML20T20" "CMP-009-00010-4" "8"				
"Resistor 10k +/-1% 0805 125 mW" "Chip Resistor, 10 KOhm, +/- 1%, 125 mW, -55 to 155 degC, 0805 (2012 Metric)" "R21, R24" "RESC2013X50X35ML15T15" "CMP-009-00018-4" "2"				
"ERJ-P06J472V" "" "R22" "RESC2013X70X40LL20T20" "CMP-2001-00487-1" "1"				
"ERJ-8ENF7681V" "" "R28" "RESC3216X70X50LL05T20" "CMP-2003-00493-1" "1"				
"LTO100FR0150JTE3" "Resistor; Thick Film; Res 0.015 Ohms; Pwr-Rtg 100 W; Tol 5%; Radial; TO-247; Heat Sink"				
"R29" "TO-247_LTO_VIS" "LTO100FR0150JTE3" "1"				
"ERA8AEB202V" "" "R31" "RESC3216X70X50ML20T25" "CMP-2003-04435-1" "1"				
"MCU Reset" "SWITCH TACTILE SPST-NO 0.05A 12V" "SW1" "CK PTS645SK43SMTR92 LFS" "Ck PTS645SK43SMTR92 LFS" "1"				
"EVQQ2W02W" "SWITCH TACTILE SPST-NO 0.02A 15V" "SW2" "FP-EVQQ2W02W-MFG"				
"CMP-05618-000028-1" "1"				
"LM7824CT" "No Description Available" "U1" "TO-220-3L_10P67X4P83_ONS" "LM7824CT" "1"				

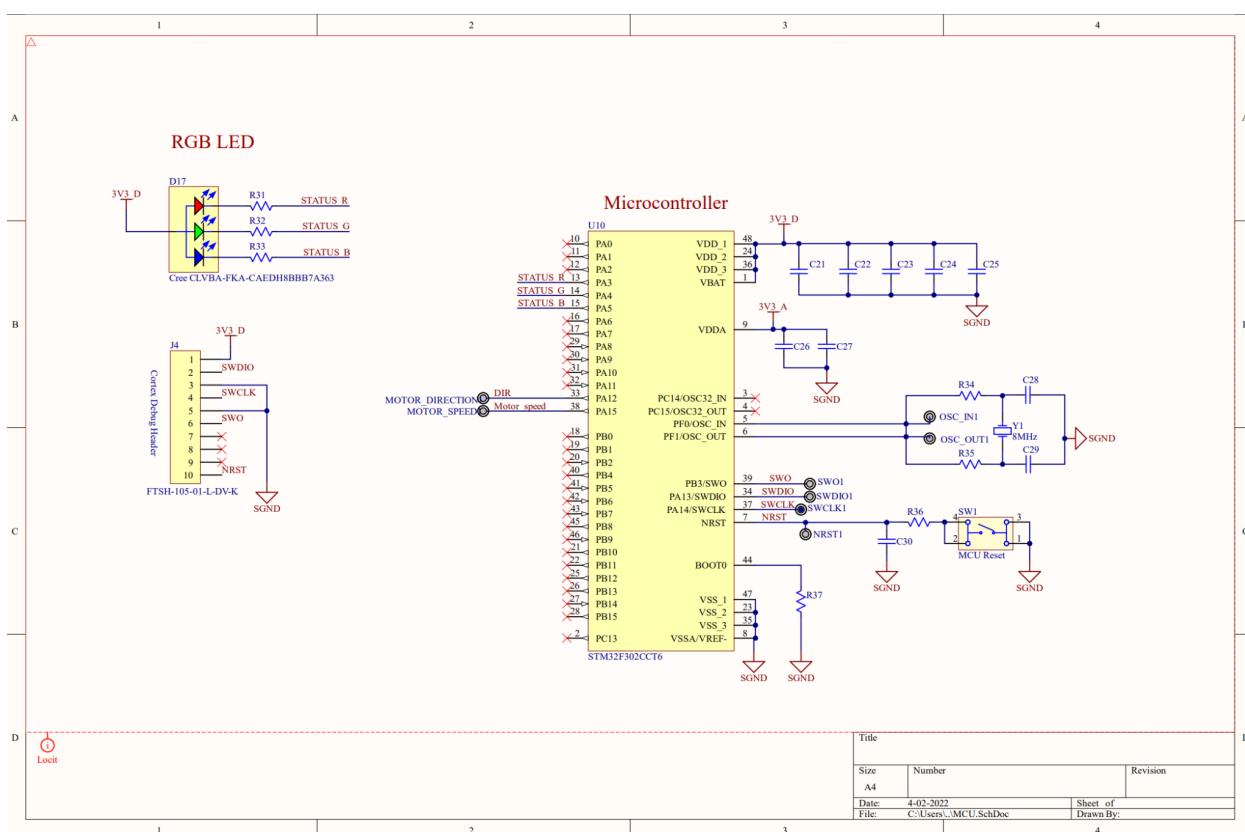
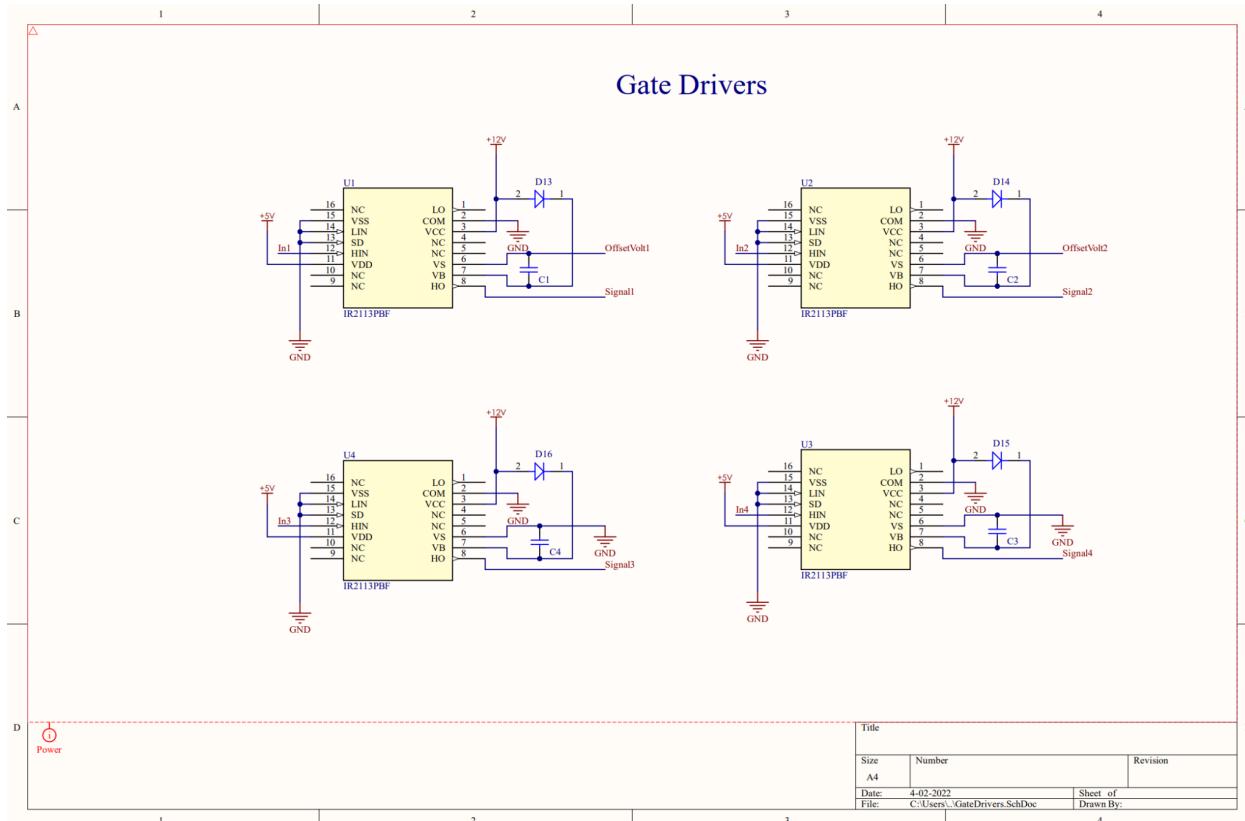
"D2TO035CR1000FTE3" "No Description Available" "U2, U3, U4, U5, U6, U7, U8" "TO-263_D2TO035_VIS"
"D2TO035CR1000FTE3" "7"
"LM340T-12" "Series 3-Terminal Positive Regulators, 3-pin TO-220" "U9" "NDE0003A"
"CMP-0062-02483-3" "1"
"IR2113PBF" "Half-Bridge Gate Driver IC Non-Inverting 14-DIP" "U10" "SOIC16_INF" "IR2113PBF" "1"
"LM7805CT" "Positive Voltage Regulator, 5 V, 1 A, -40 to 125 degC, 3-Pin TO-220, RoHS, Tube" "U11"
"FAIR-TO-220-3" "CMP-2000-04938-1" "1"
"STM32F302CCT6" "ARM® Cortex®-M4 STM32F3 Microcontroller IC 32-Bit 72MHz 256KB (256K x 8) FLASH 48-LQFP (7x7)"
"U12" "STMicroelectronics STM32F302C8T6 (48-LQFP)" "STMicroelectronics STM32F302CCT6" "1"
"ADJ45048" "No Description Available" "U13" "RELAY_ADJ450_PAN" "ADJ45048" "1"
"LM1458MX/NOPB" "IC OPAMP GP 2 CIRCUIT 8SOIC" "U14" "FP-D0008A-IPC_B" "CMP-04895-000419-1"
"1"
"8MHz" "8MHz ±20ppm Crystal 18pF 140 Ohms 2-SMD, No Lead" "Y1" "ABRACON ABM3-8.000MHZ-D2Y-T" "8MHz
Oscillator" "1"

APPENDIX B

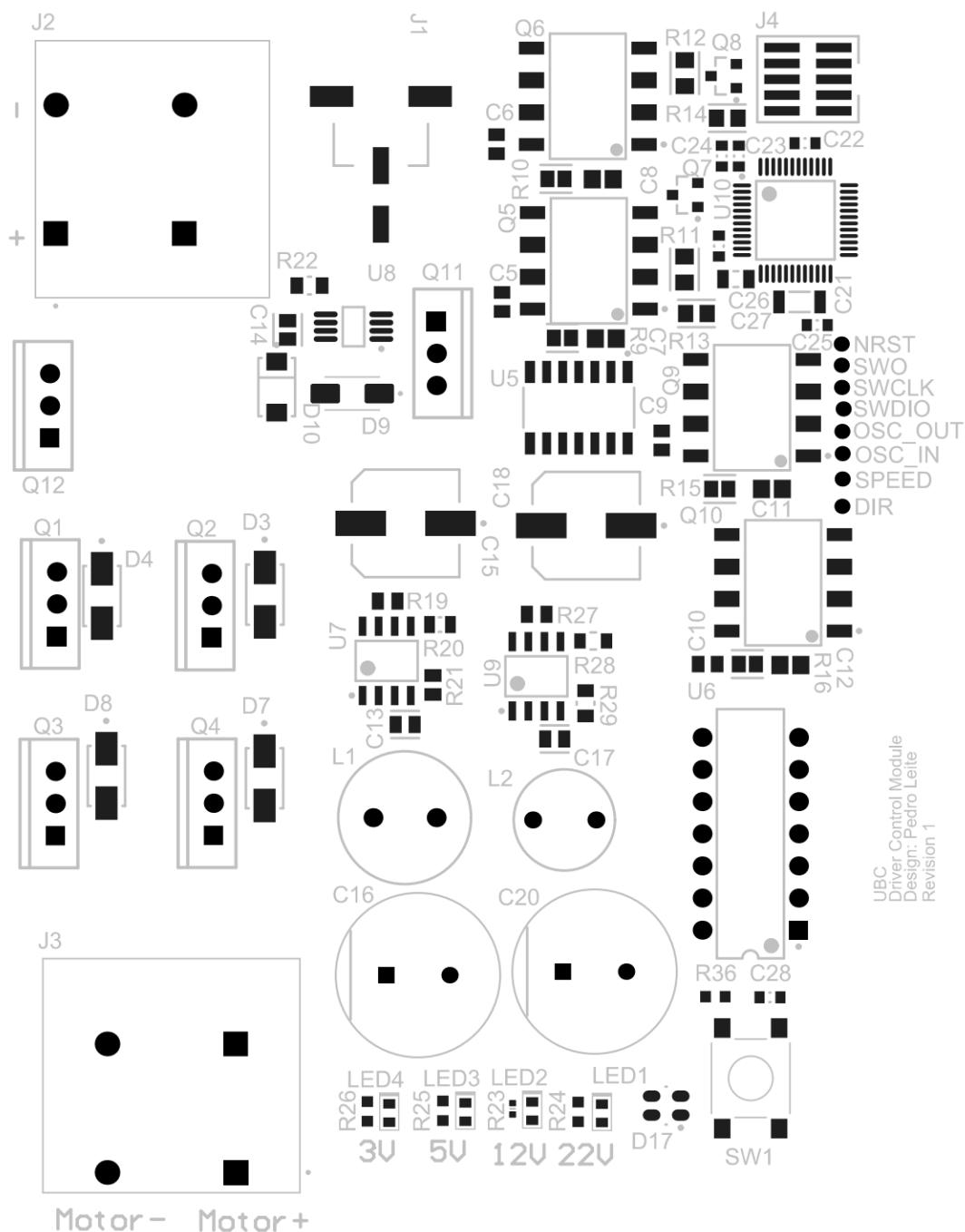
Driver control Module



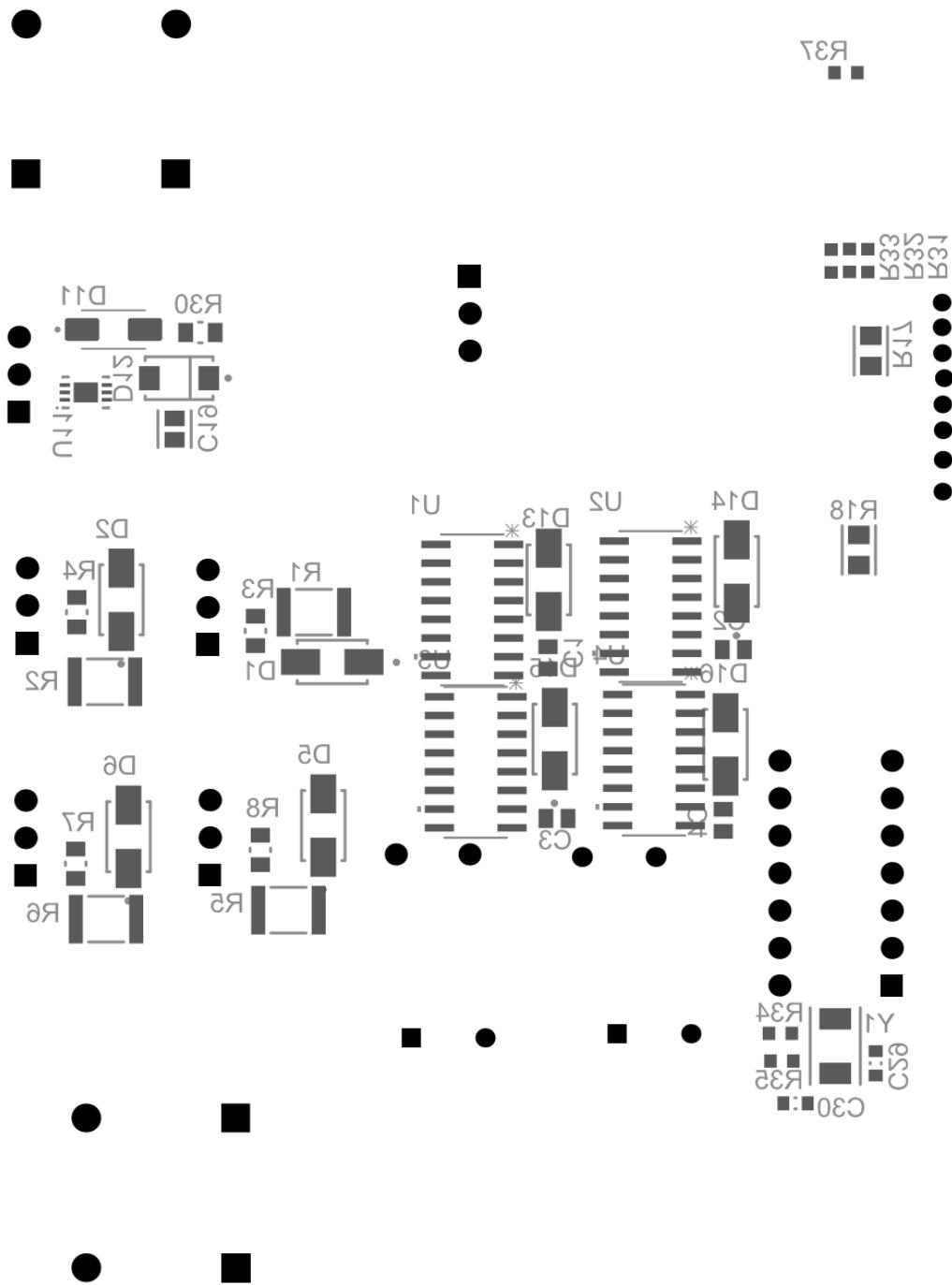




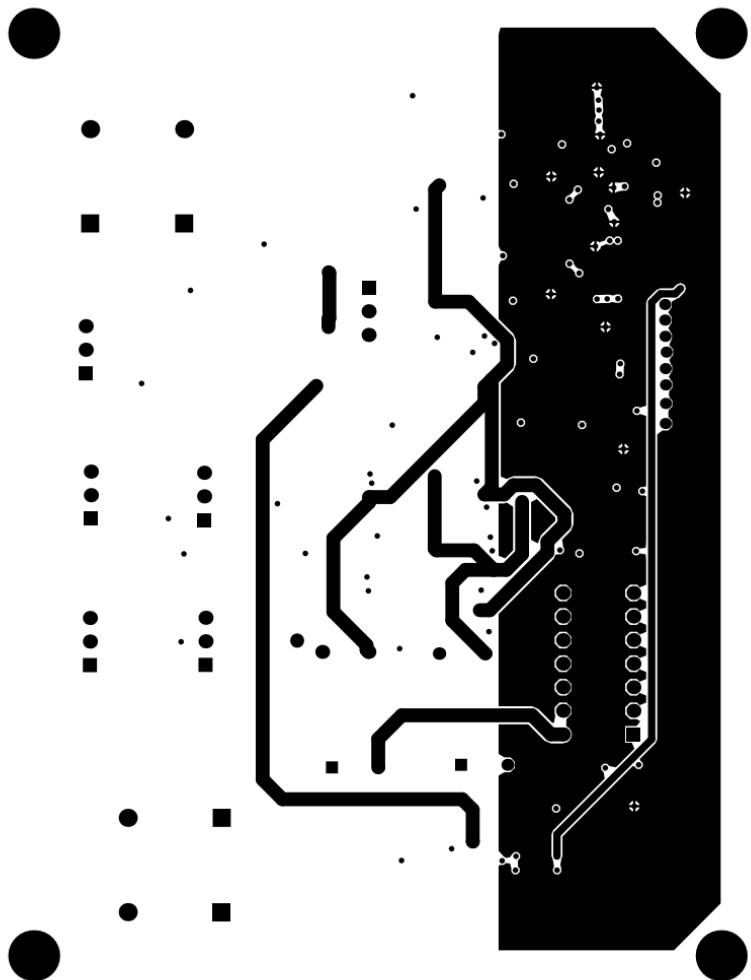
Top Layer



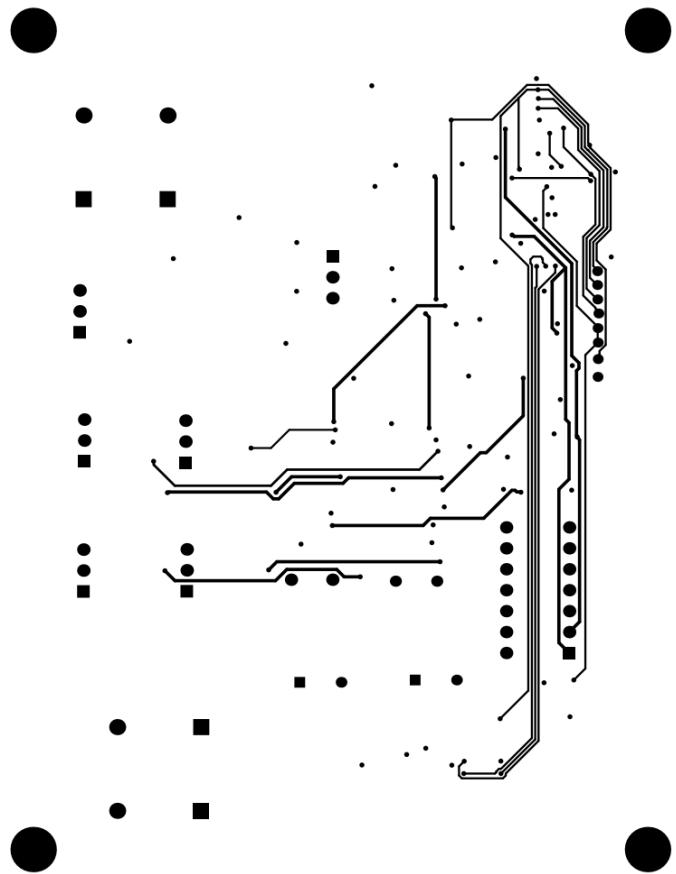
Bottom Layer



Signal layer 1



Signal Layer 2



Bill Of Material

Description	Designator	Footprint	LibRef	Quantity	Category
"" "C1, C2, C3, C4, C5, C6, C9, C10" "[NoParam], Ceramic Capacitors"		"CAPC2013X135X45LL10T25"		"CMP-1036-04761-2"	"8"
"" "C7, C8, C11, C12" "CAPC2013X94X50NL20T25" "CMP-2007-04377-1"				"4"	"Ceramic Capacitors"
"CAP CER 470PF 50V X7R 0805" "C13, C17"		"FP-C0805C-DN-MFG"		"CMP-03020-010032-1"	"2"
"Cap"					
"CL21 Series 0805 100nF 25V ±10% Tolerance X7R Multilayer Ceramic Chip Capacitor" "C14, C19" "FP-CL21-IPC_C"					
"CMP-13271-002854-1" "2" ""					
"CAP ALUM 100UF 20% 50V SMD" "C15, C18"		"FP-FKF-MFG"	"CMP-2000-06208-3"	"2"	""
"CAP ALUM 470UF 20% 50V RADIAL" "C16, C20"		"FP-EEUFM1H471-MFG"	"CMP-05427-000073-1"	"2"	
""					
"" "C21" "1206 CAPACITOR (TDK C-SERIES)" "1206 Ceramic Capacitor" "1" ""					
"" "C22, C23, C24, C25, C26, C28, C29, C30" "0603 CAPACITOR (TDK C-SERIES)" "0603 Ceramic Capacitor" "8"					
"" ""					
"" "C27" "0805 CAPACITOR (TDK C-SERIES)" "0805 Ceramic Capacitor" "1" ""					
"DIODE GEN PURP 1KV 1A SMA" "D1, D2, D3, D4, D5, D6, D7, D8, D13, D14, D15, D16" "FP-403AE-MFG"					
"CMP-2000-04942-3" "12" ""					
"SMAT70A-13, Protection Tvs Unid Irectional Sensor-peizoresist" "D9, D11" "DIOM5226X230N" "SMAT70A-13" "2"					
"TVS Diodes"					
"TVS DIODE 24V 50V SMA" "D10, D12" "FP-SMA-MFG" "CMP-12225-000049-1" "2" "Diode"					
"RGB LED" "D17" "Cree CLVBA-FKA-Series (4-SOJ)" "Cree CLVBA-FKA-CAEDH8BBB7A363" "1" ""					
"CONN HEADER SMD R/A 2POS" "J1" "Molex 0430450209" "CMP-029-000006-1" "1" ""					
"2 Posn Power Connector, Black, 10.16mm, 1-1986660-" "J2, J3" "TE_1-1986660-2" "2Pin_HighCurrent" "2"					
"10-Pin 1.27mm Shrouded Cortex Debug Connector" "J4" "Samtec FTSH-105-01-L-DV-K" "Samtec FTSH-105-01-L-DV-K" "1" ""					
"Radial Leaded Wire Wound Inductor WE-TI, L=220 μH" "L1" "WE-TI 1014" "CMP-1405-00005-1" "1"					
""					
"Radial Leaded Wire Wound Inductor WE-TI, L = 100 μH" "L2" "WE-TI-LB" "CMP-0225-00065-1" "1"					
""					
"LED GREEN CLEAR CHIP SMD" "LED1, LED2, LED3, LED4" "Lite-On LTST-C193KGKT-5A GREEN (1608)" "CMP-026-000009-1" "4" ""					
"" "MOTOR_DIRECTION1, MOTOR_SPEED1, NRST1, OSC_IN1, OSC_OUT1, SWCLK1, SWDIO1, SWO1" "TESTPOINT" "CMP-020-0001-1" "8" ""					
"N-Channel 100 V 55A (Tc) 200W (Tc) Through Hole TO-220AB" "Q1, Q2, Q3, Q4, Q11, Q12" "IRL2910" "IRL2910PBF" "6" "MOSFETs"					
"OPTOISO 3.75KV OPN COLL 8DIP GW" "Q5, Q6, Q9, Q10" "FP-6N137-300E-MFG" "CMP-18400-000015-1" "4" "Trans"					
"Small Signal MOSFET, 30 V, 0.56 A, Single N-Channe, 3-Pin SOT-23, Pb-Free, Tape and Reel" "ONSC-SOT-23-3-318-08_V" "CMP-1058-00759-1" "2" ""					
"10R 0.75W 1% 1812 (4532 Metric) SMD" "R1, R2, R5, R6" "RESC1812(4532)_L" "CMP-1016-00264-1" "4" ""					
"10kΩ ±1% 0.25W 0805 High Power Anti-Sulfur Thin Film Chip Resistor" "R3, R4, R7, R8, R9, R10, R15, R16" "FP-RNCP0805-MFG, FP-RNCP0805-IPC_C" "CMP-26527-007436-1" "8" "[NoParam], Chip SMD Resistors"					
"100Ω ±0.5% 0.125W Chip Resistor 0805 Thick Film AEC-Q200 Qualified" "R11, R12, R17, R18" "FP-RK73G2A-IPC_A" "CMP-04015-102025-1" "4" ""					
"RES 100K OHM 0.1% 1/8W 0805" "R13, R14" "FP-ERA6A-IPC_B" "CMP-2001-00583-2" "2" ""					
"" "R19, R27" "RESC2013X70X40LL20T20" "CMP-2001-00468-1" "2" "Chip SMD Resistors"					
"" "R20" "RESC2013X50X30LL20T20" "CMP-2001-03882-1" "1" "Chip SMD Resistors"					
"" "R21" "RESC2013X60X40LL20T25" "CMP-2001-00589-1" "1" "Chip SMD Resistors"					
"1kΩ ±1% 0.25W 0805 High Power Anti-Sulfur Thin Film Chip Resistor" "R22, R29, R30" "FP-RNCP0805-MFG" "CMP-26527-001902-1" "3" ""					
"Chip Resistor, 1 kOhms, +/-5 %, 63 mW, -55 to 155 degC, 0402" "R23" "RESC0402(1005)_L" "CMP-009-00157-2" "1" ""					
""					
"" "R24" "0603 RESISTOR (YAGEO)" "0603 Resistor_2" "1" ""					
"" "R25, R31, R32, R33, R34, R35, R36, R37" "0603 RESISTOR (YAGEO)" "0603 Resistor" "8" ""					
"Res Thick Film 0603 560 Ohm 1% 0.25W(1/4W) +/-100ppm/C Molded SMD Automotive Punched T/R" "R26" "0603 RESISTOR (YAGEO)" "0603 Resistor_1" "1" "Chip SMD Resistors"					
"RES 8.45K OHM 1/8W .1% SMD 0805" "R28" "FP-RT0805-MFG" "CMP-03412-018377-1" "1" "Res"					

"SWITCH TACTILE SPST-NO 0.05A 12V" "SW1" "CK PTS645SK43SMTR92 LFS" "Ck PTS645SK43SMTR92
LFS" "1" ""
"Half-Bridge Gate Driver IC Non-Inverting 14-DIP" "U1, U2, U3, U4" "SOIC16_INF" "IR2113PBF" "4" ""
"IC INVERTER SCHMITT 6CH 14SO" "U5" "FP-SOT108-1-MFG" "CMP-14350-000004-1" "1" ""
"Hex inverters with open collector outputs, N0014A, TUBE" "U6" "N0014A" "CMP-1615-00873-2" "1" ""
"Step-Up / Down / Inverting Switching Regulator, 1.5 A, 3 to 40 V, 0 to 70 degC, 8-Pin SOIC (751-07), RoHS, Tube" "U7, U9"
"ONSC-SOIC-8-751-07_V" "CMP-2000-04925-1" "2" ""
"Ideal Diode Controller with Reverse Input Protection, 4 to 80 V Vin, 8-pin SOP (MS8-8), -40 to 85 degC, Pb-Free" "U8"
"LT-MS8-8_M" "CMP-0479-00203-1" "1" ""
"ARM® Cortex®-M4 STM32F3 Microcontroller IC 32-Bit 72MHz 256KB (256K x 8) FLASH 48-LQFP (7x7)" "U10"
"STMicroelectronics STM32F302C8T6 (48-LQFP) - duplicate" "STMicroelectronics STM32F302CCT6" "1" ""
"Ideal Diode Controller with Reverse Input Protection, 4 to 80 V Vin, 6-pin SON (DCB-6), -40 to 85 degC, Pb-Free, Mini Tape and
Reel" "U11" "LT-DCB-6_V" "CMP-0479-00018-1" "1" ""
"8MHz ±20ppm Crystal 18pF 140 Ohms 2-SMD, No Lead" "Y1" "ABRACON ABM3-8.000MHZ-D2Y-T" "8MHz Oscillator"
"1" ""

APPENDIX C

Quadrature encoder

```
`default_nettype none
module quadrature_counter(clk, A, B, counter, out, reset);

input logic clk, A, B, reset; // A and B are output channel from encoder, Reset is
homing logic interrupt
output logic [9:0] out; //keeps the track of position

logic [1:0] state; //state machine state
logic [1:0] in;
logic [9:0] counter;

assign in = {A,B}; //concat the inputs

parameter [1:0] s0= 2'b00;
parameter [1:0] s1= 2'b01;
parameter [1:0] s2= 2'b10;
parameter [1:0] s3= 2'b11;

always_ff(posedge clk or posedge reset) begin
    if(reset) begin //Homing logic
        counter <= 10'd500;
        state <= s0;
    end
    else begin //counter state machine
        case(state)
            s0: if(in == 2'b01) begin
                if(counter! = 10'd1) begin //only subtract if count is not 1 because 1
represents 499 anticlockwise rotations and next anticlockwise rotation will be home
                    counter <= counter - 10'd1;
                    state <= 2'b01;
                end
                else begin
                    counter <= 10'd500;
                    state <= 2'b01;
                end
            end
            else if(in == 2'b10) begin
                if(counter!=10'd999) begin //only add if count is not 999 because 999
represents 499 clockwise rotations and next clockwise rotation will be home
                    counter <= counter + 10'd1
                    state <= 2'b10;
                end
                else begin
                    counter <= 10'd500;
                    state <= 2'b10;
                end
            end
        end
    end
    s1: if(in == 2'b11) begin
        if(counter! = 10'd1) begin
```

```

        counter <= counter - 10'd1;
        state <= 2'b11;
    end
    else begin
        counter <= 10'd500;
        state <= 2'b11;
    end
end
else if(in == 2'b00) begin
    if(counter!=10'd999) begin
        counter <= counter + 10'd1
        state <= 2'b00;
    end
    else begin
        counter <= 10'd500;
        state <= 2'b00;
    end
end
end

s2: if(in == 2'b00) begin
    if(counter! = 10'd1) begin
        counter <= counter - 10'd1;
        state <= 2'b00;
    end
    else begin
        counter <= 10'd500;
        state <= 2'b00;
    end
end
else if(in == 2'b11) begin
    if(counter!=10'd999) begin
        counter <= counter + 10'd1
        state <= 2'b11;
    end
    else begin
        counter <= 10'd500;
        state <= 2'b11;
    end
end
end

s3: if(in == 2'b10) begin
    if(counter! = 10'd1) begin
        counter <= counter - 10'd1;
        state <= 2'b10;
    end
    else begin
        counter <= 10'd500;
        state <= 2'b10;
    end
end
else if(in == 2'b01) begin
    if(counter!=10'd999) begin
        counter <= counter + 10'd1
        state <= 2'b01;
    end
end

```

```
        else begin
            counter <= 10'd500;
            state <= 2'b01;
        end
    end
endcase
end
end

always_ff(posedge clk) begin //compute position
    if(counter >= 10'd500) begin
        out <= counter - 10'd500;
    end
    else begin
        out <= counter;
    end
end
endmodule
```

APPENDIX D

Mosfet

**International
IR Rectifier**

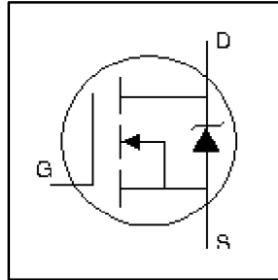
PRELIMINARY

PD 9.1375

IRL2910

HEXFET® Power MOSFET

- Logic-Level Gate Drive
- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated

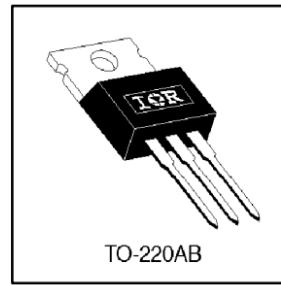


$V_{DSS} = 100V$
 $R_{DS(on)} = 0.026\Omega$
 $I_D = 48A$

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design for which HEXFET Power MOSFETs are well known, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	48	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	34	
I_{DM}	Pulsed Drain Current ①	190	
$P_D @ T_C = 25^\circ C$	Power Dissipation	150	W
	Linear Derating Factor	1.0	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②	520	mJ
I_{AR}	Avalanche Current ①③	29	A
E_{AR}	Repetitive Avalanche Energy ①	15	mJ
dv/dt	Peak Diode Recovery dv/dt ③	7.4	V/ns
T_J	Operating Junction and	-55 to + 175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds		
	Mounting torque, 6-32 or M3 screw	10 lbf-in (1.1N·m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	1.0	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.50	—	°C/W
$R_{\theta JA}$	Junction-to-Ambient	—	62	°C/W